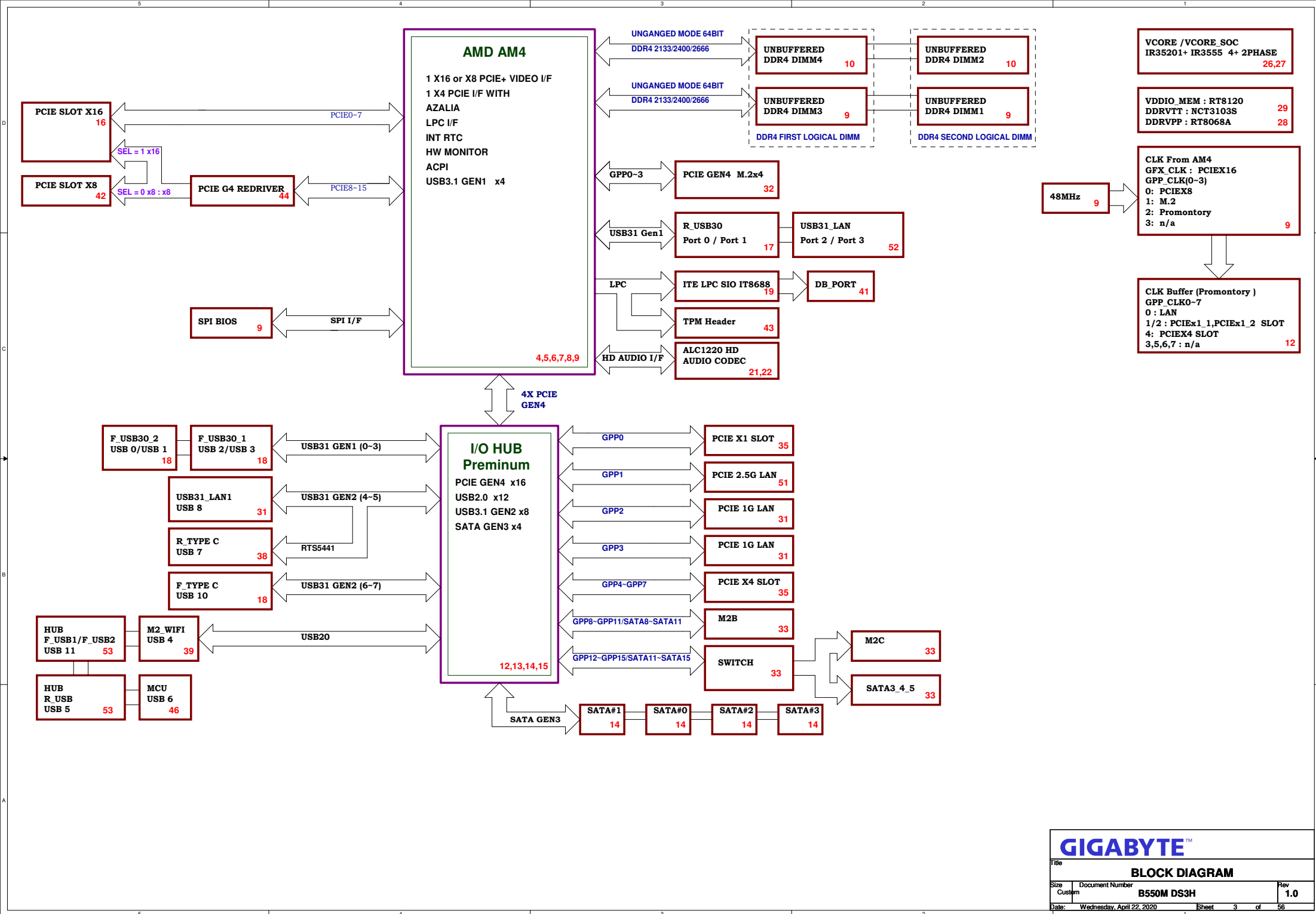


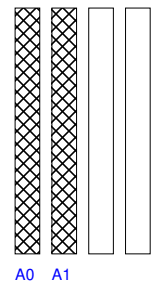
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| 5 | | | | | 4 | | | | | 3 | | | | | 2 | | | | | 1 | | | | |
| B550M DS3H | | | | | | | | | | | | | | | | | | | | | | | | |
| PAGE | | | | | TITLE | | | | | PAGE | | | | | TITLE | | | | | | | | | |
| | | | | | | | | | | 32 | | | | | A_VDD1V8 | | | | | | | | | |
| 01 | | | | | COVER SHEET | | | | | 33 | | | | | M2A, M2-WIFI | | | | | | | | | |
| 02 | | | | | BOM & PCB MODIFY HISTORY | | | | | 34 | | | | | M2B | | | | | | | | | |
| 03 | | | | | BLOCK DIAGRAM | | | | | 35 | | | | | HDMI + DVI | | | | | | | | | |
| 04 | | | | | CPU DDR4 MEMORY | | | | | 36 | | | | | R/F_USB30, KB_MS_USB, F_USB | | | | | | | | | |
| 05 | | | | | CPU CONTROL | | | | | 37 | | | | | RTL8111G | | | | | | | | | |
| 06 | | | | | CPU GFX, GPP, SB, GND | | | | | 38 | | | | | Realtek ALC887 | | | | | | | | | |
| 07 | | | | | CPU ACPI/GPIO/USB/AUDIO | | | | | 39 | | | | | REAR AUDIO JACK | | | | | | | | | |
| 08 | | | | | CPU POWER & GND | | | | | 45 | | | | | ATX ,F_PANEL | | | | | | | | | |
| 09 | | | | | CPU CLK/SPI/USB | | | | | 46 | | | | | IT5702 | | | | | | | | | |
| 10 | | | | | DDR4 CHANNEL A | | | | | 47 | | | | | CPU / IO / DDR LED / C_LED | | | | | | | | | |
| 11 | | | | | DDR4 CHANNEL B | | | | | 48 | | | | | D_LED | | | | | | | | | |
| 12 | | | | | PM CLK/GPIO/FAN | | | | | 48 | | | | | BOTTOM | | | | | | | | | |
| 13 | | | | | | | | | | | | | | | | | | | | | | | | |

<

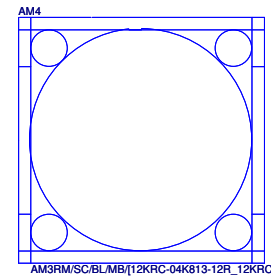
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MEM CHA



- [10] MODT_A[0..3] <-- MODT_A[0..3]
- [10] MDA[0..63] <-- MDA[0..63]
- [10] MAAA[0..17] <-- MAAA[0..17]
- [10] DQSA[0..8] <-- DQSA[0..8]
- [10] -DQSA[0..8] <-- -DQSA[0..8]



2020.02.17
12KRC-04K813-12R/14R
抽芽式

- [11] MODT_B[0..3] <-- MODT_B[0..3]
- [11] MDB[0..63] <-- MDB[0..63]
- [11] MAAB[0..17] <-- MAAB[0..17]
- [11] DQSB[0..8] <-- DQSB[0..8]
- [11] -DQSB[0..8] <-- -DQSB[0..8]

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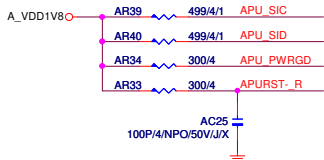
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Size: Custom Document Number: **B550M DS3H** Rev: **1.0**

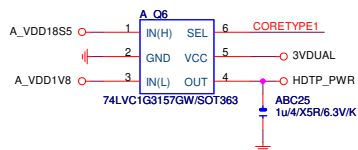
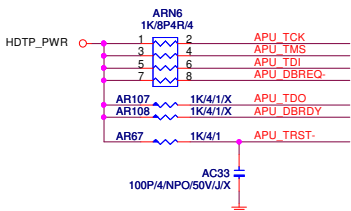
Date: Wednesday, April 22, 2020 Sheet: 4 of 56

A0 A1

B0 B1

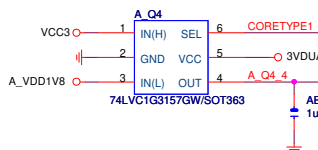
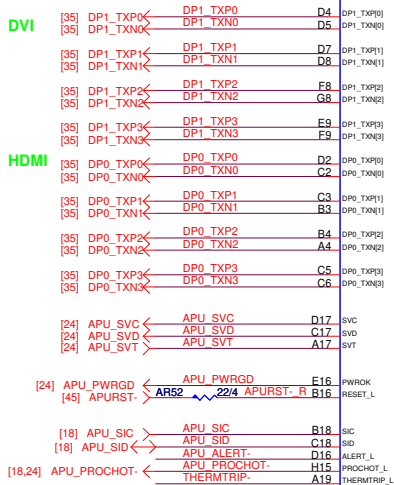


| SVC | SVD | Boot voltage |
|-----|-----|--------------|
| 0 | 0 | 1.1 |
| 0 | 1 | 1.0 |
| 1 | 0 | 0.9 |
| 1 | 1 | 0.8 |



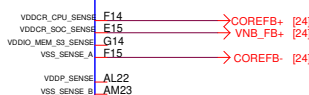
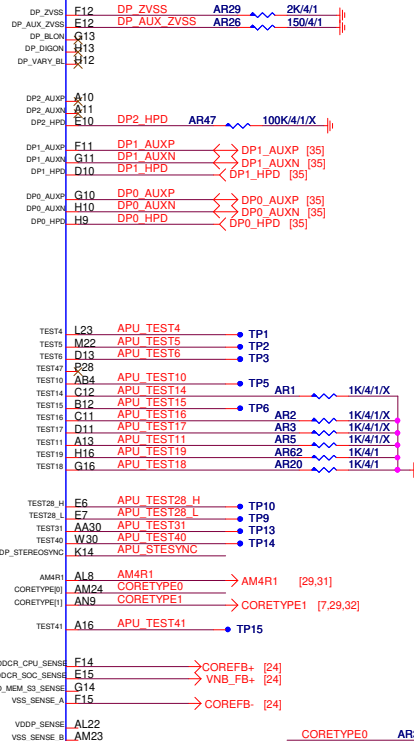
DVI

HDMI

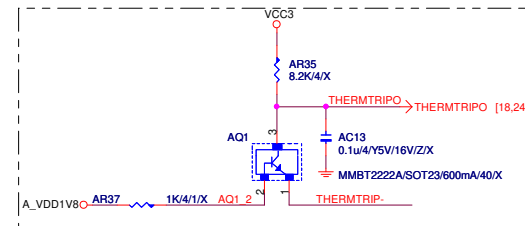


AM REV 0.92
PART 3 OF 12

Placed within 1500 mils from APU



APU_STESYNC: high=>HDMI, low=>NO HDMI

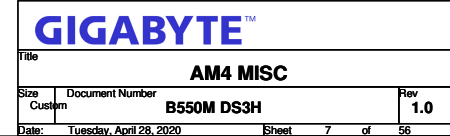


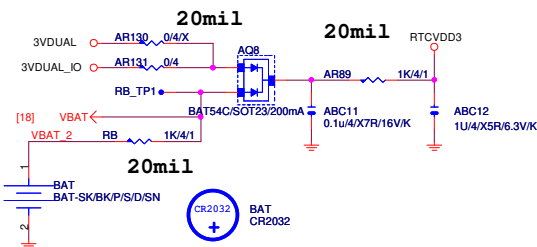
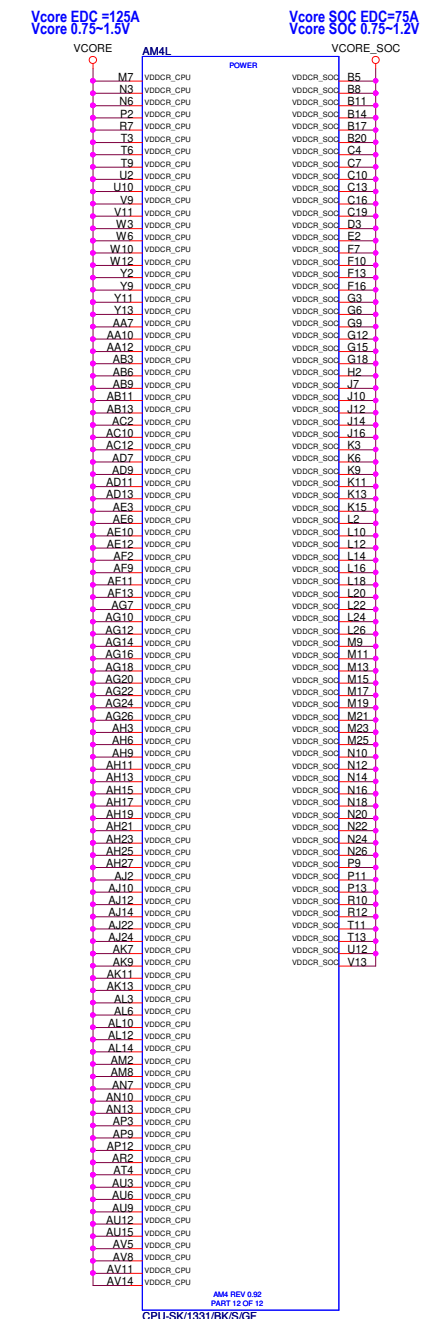
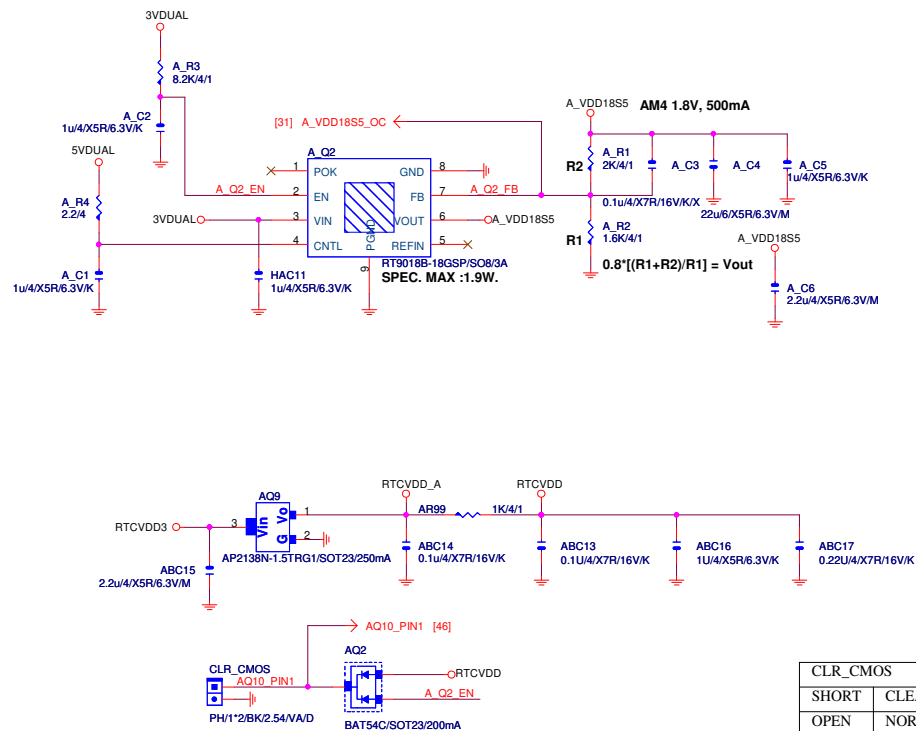
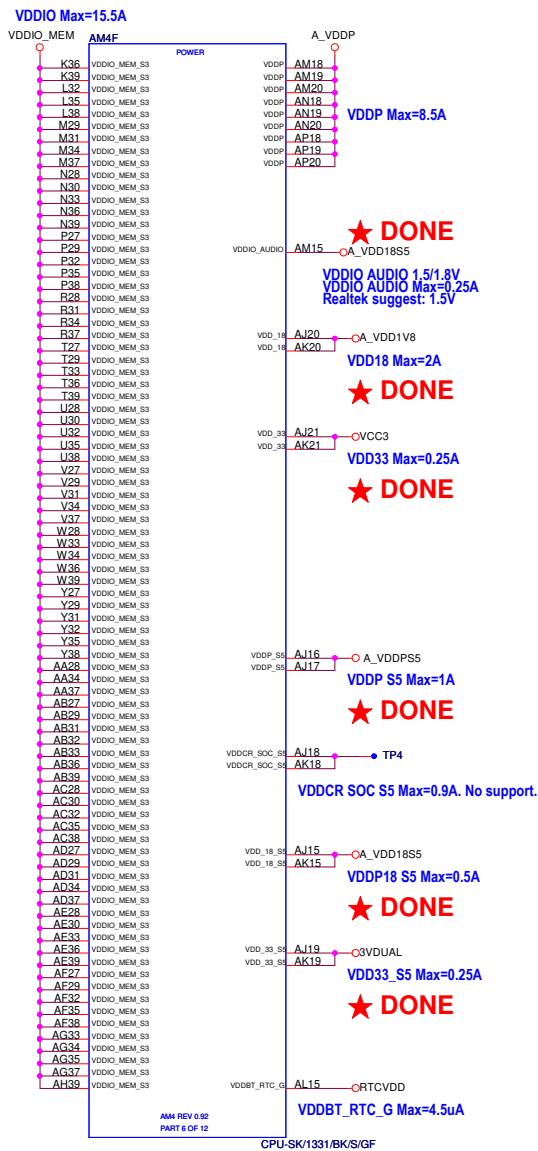
AM4 CPU CoreType

| CORETYPE 1 | CORETYPE 0 | Family / Model Numbers | AM4 APU TYPE |
|------------|------------|--------------------------------|--------------|
| 0 BR | 0 | Family 15 h / Models 60 h-6 Fh | TYPE 0 |
| 0 ST | 1 | Reserved | TYPE 1 |
| 1 ZP | 0 | Family 17 h / Models 00 h-0 Fh | TYPE 2 |
| 1 RV | 1 | Family 17 h / Models 10 h-1 Fh | TYPE 3 |

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| CPU CONTROL | | |
|-------------|----------------------|---------------|
| Title | Document Number | Rev |
| Size | B550M DS3H | 1.0 |
| Date: | Friday, May 29, 2020 | Sheet 5 of 56 |





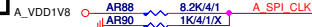
| CLR_CMOS | |
|----------------------------|------------|
| SHORT | CLEAR CMOS |
| OPEN | NORMAL |
| NOT ADD ICT FOR RTCVDD PIN | |

| GIGABYTE™ | | | |
|-----------------|-------------------------|-------|---------|
| Title | | | |
| CPU POWER & GND | | | |
| Size | Document Number | Rev | |
| Custom | B550M DS3H | 1.0 | |
| Date: | Tuesday, April 28, 2020 | Sheet | 8 of 56 |



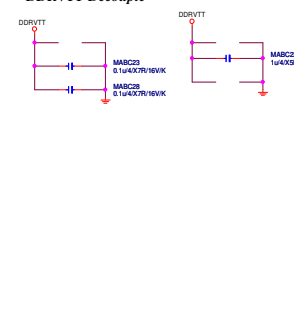
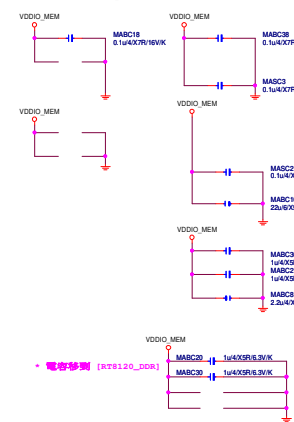
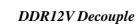
| | SPI_CLK | LFRAME- | SYS_RST- | LPC_CLK0 | LPC_CLK1 |
|-----------|---------------------|---------|-------------------|---|------------------------------|
| PULL HIGH | Internal clock mode | SPI ROM | Normal reset mode | PSP modify SPI page reg bits[24:24] | Use 48MHz crystal clock |
| PULL LOW | Extal clock mode | LPC ROM | Short reset mode | PSP not modify SPI page reg bits[24:24] | Use 100MHz extl clock input. |

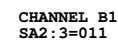
Bule: default

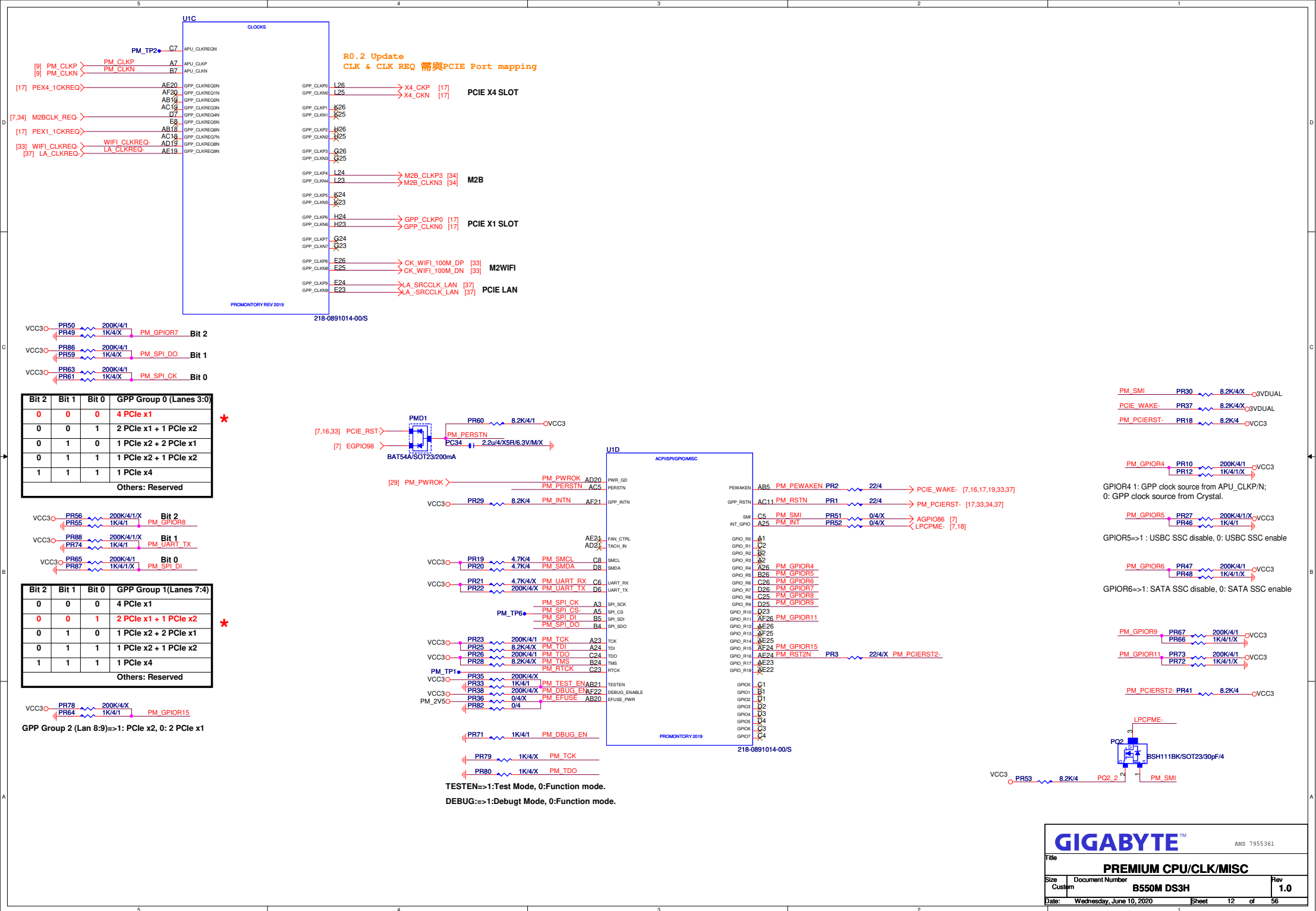


Layout colay 128Mx1

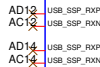
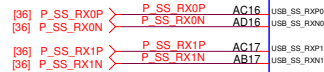
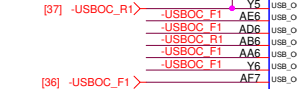






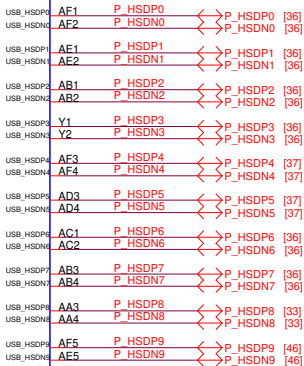


USB port power control 9:0
(VCC3). Output.



PROMONTORY REV 2019 218-0891014-00/S

| USB32G2 | USB20 | USB_OC |
|---------|-------|--------|
| 0 | 0 | 0 |
| 1 | 1 | 1 |
| USB32G1 | | |
| 0 | 2 | 2 |
| 1 | 3 | 3 |
| | 4 | 4 |
| | 5 | 5 |
| | 6 | 6 |
| | 7 | 7 |
| | 8 | 7 |
| | 9 | 7 |



KB_MS_USB OK

KB_MS_USB OK

F_USB30 OK

F_USB30 OK

LAN_USB OK

LAN_USB OK

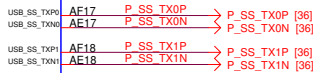
F_USB20 OK

F_USB20 OK

M2 WIFI OK

MCU OK

USB 3.1 Gen 1



HSD 2 F_USB30 OK

HSD 3 F_USB30 OK

USB 3.1 Gen 2



HSD 0

HSD 1

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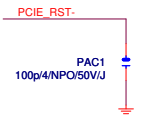
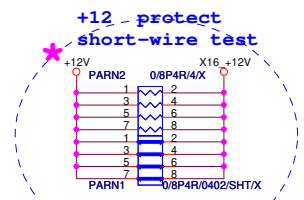
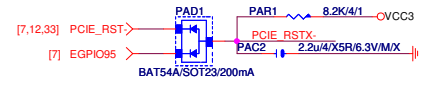
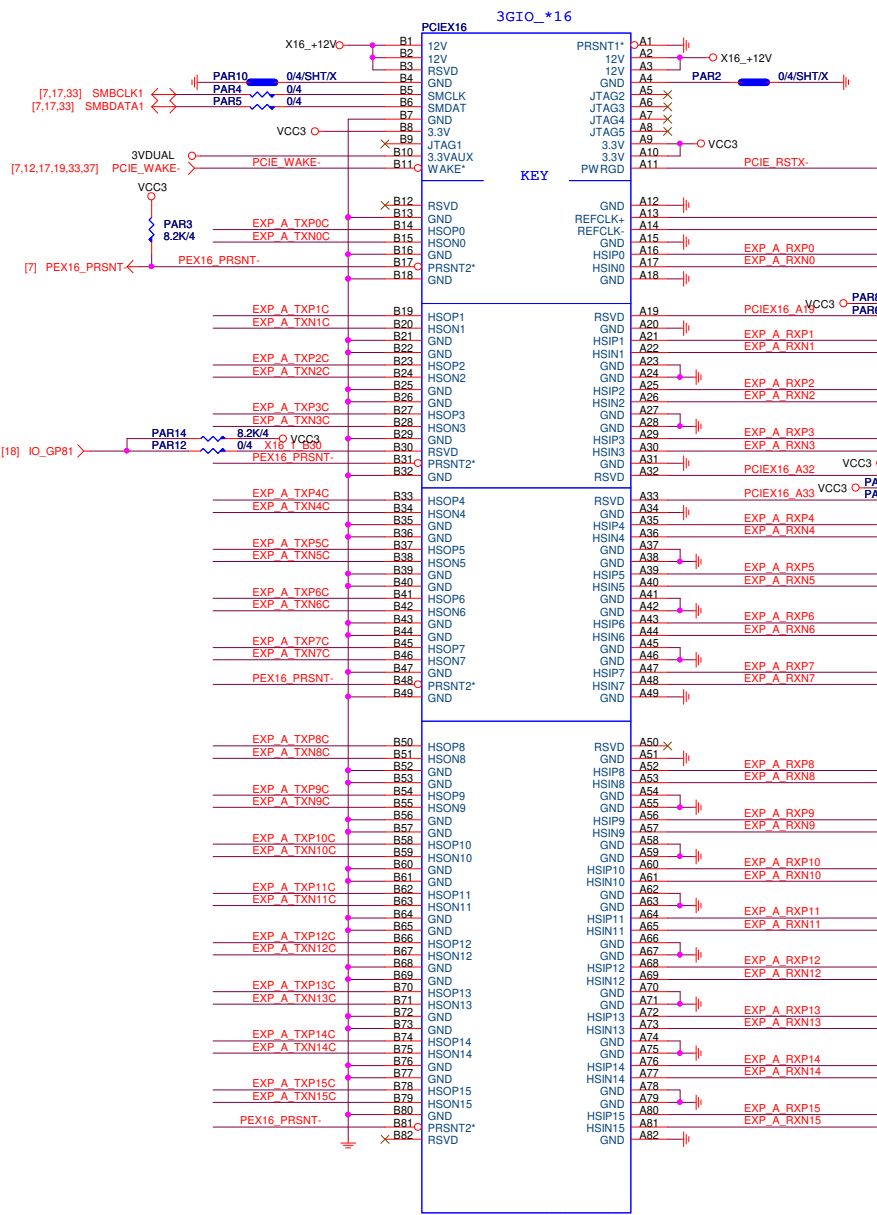
ANS 7955361

Title PM USB

Size Custom Document Number B550M DS3H

Rev 1.0

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| | | | |
|-------------|-------|------------------|--------------|
| EXP A TXP0 | PAC4 | 0.22u4/X5R6.3V/K | EXP A TXP0C |
| EXP A TXN0 | PAC5 | 0.22u4/X5R6.3V/K | EXP A TXN0C |
| EXP A TXP1 | PAC6 | 0.22u4/X5R6.3V/K | EXP A TXP1C |
| EXP A TXN1 | PAC7 | 0.22u4/X5R6.3V/K | EXP A TXN1C |
| EXP A TXP2 | PAC8 | 0.22u4/X5R6.3V/K | EXP A TXP2C |
| EXP A TXN2 | PAC9 | 0.22u4/X5R6.3V/K | EXP A TXN2C |
| EXP A TXP3 | PAC10 | 0.22u4/X5R6.3V/K | EXP A TXP3C |
| EXP A TXN3 | PAC11 | 0.22u4/X5R6.3V/K | EXP A TXN3C |
| EXP A TXP4 | PAC12 | 0.22u4/X5R6.3V/K | EXP A TXP4C |
| EXP A TXN4 | PAC13 | 0.22u4/X5R6.3V/K | EXP A TXN4C |
| EXP A TXP5 | PAC14 | 0.22u4/X5R6.3V/K | EXP A TXP5C |
| EXP A TXN5 | PAC15 | 0.22u4/X5R6.3V/K | EXP A TXN5C |
| EXP A TXP6 | PAC16 | 0.22u4/X5R6.3V/K | EXP A TXP6C |
| EXP A TXN6 | PAC17 | 0.22u4/X5R6.3V/K | EXP A TXN6C |
| EXP A TXP7 | PAC18 | 0.22u4/X5R6.3V/K | EXP A TXP7C |
| EXP A TXN7 | PAC19 | 0.22u4/X5R6.3V/K | EXP A TXN7C |
| EXP A TXP8 | PAC20 | 0.22u4/X5R6.3V/K | EXP A TXP8C |
| EXP A TXN8 | PAC21 | 0.22u4/X5R6.3V/K | EXP A TXN8C |
| EXP A TXP9 | PAC22 | 0.22u4/X5R6.3V/K | EXP A TXP9C |
| EXP A TXN9 | PAC23 | 0.22u4/X5R6.3V/K | EXP A TXN9C |
| EXP A TXP10 | PAC24 | 0.22u4/X5R6.3V/K | EXP A TXP10C |
| EXP A TXN10 | PAC25 | 0.22u4/X5R6.3V/K | EXP A TXN10C |
| EXP A TXP11 | PAC26 | 0.22u4/X5R6.3V/K | EXP A TXP11C |
| EXP A TXN11 | PAC27 | 0.22u4/X5R6.3V/K | EXP A TXN11C |
| EXP A TXP12 | PAC28 | 0.22u4/X5R6.3V/K | EXP A TXP12C |
| EXP A TXN12 | PAC29 | 0.22u4/X5R6.3V/K | EXP A TXN12C |
| EXP A TXP13 | PAC30 | 0.22u4/X5R6.3V/K | EXP A TXP13C |
| EXP A TXN13 | PAC31 | 0.22u4/X5R6.3V/K | EXP A TXN13C |
| EXP A TXP14 | PAC32 | 0.22u4/X5R6.3V/K | EXP A TXP14C |
| EXP A TXN14 | PAC33 | 0.22u4/X5R6.3V/K | EXP A TXN14C |
| EXP A TXP15 | PAC34 | 0.22u4/X5R6.3V/K | EXP A TXP15C |
| EXP A TXN15 | PAC35 | 0.22u4/X5R6.3V/K | EXP A TXN15C |

| | | |
|----------------|-------------------|-----|
| EXP A RXP0.15] | >>>EXP_A_RXP0.15] | [6] |
| EXP A RXN0.15] | >>>EXP_A_RXN0.15] | [6] |
| EXP A TXP0.15] | >>>EXP_A_TXP0.15] | [6] |
| EXP A TXN0.15] | >>>EXP_A_TXN0.15] | [6] |

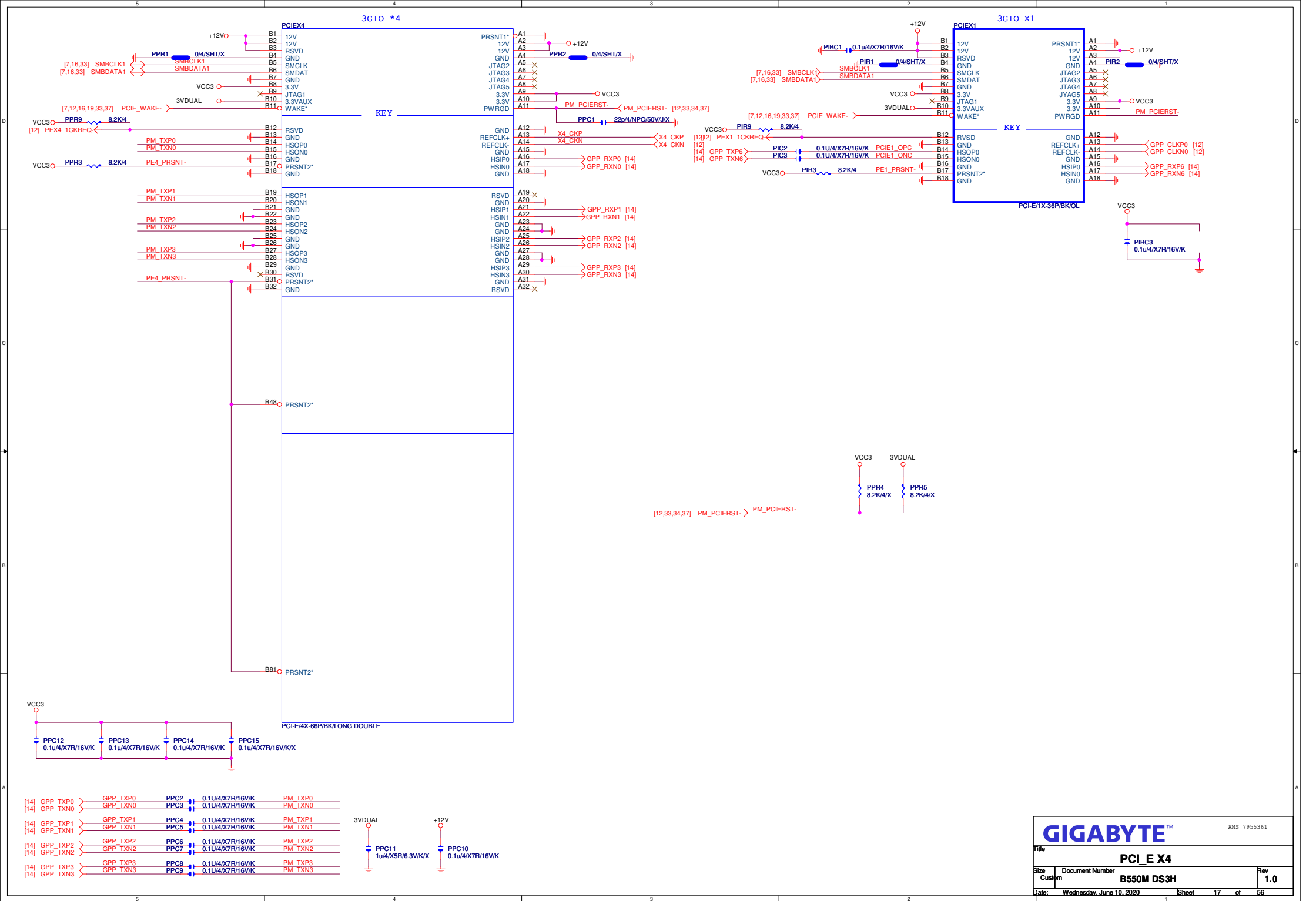


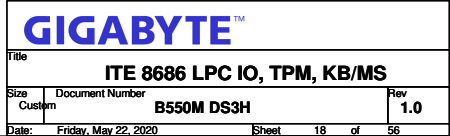
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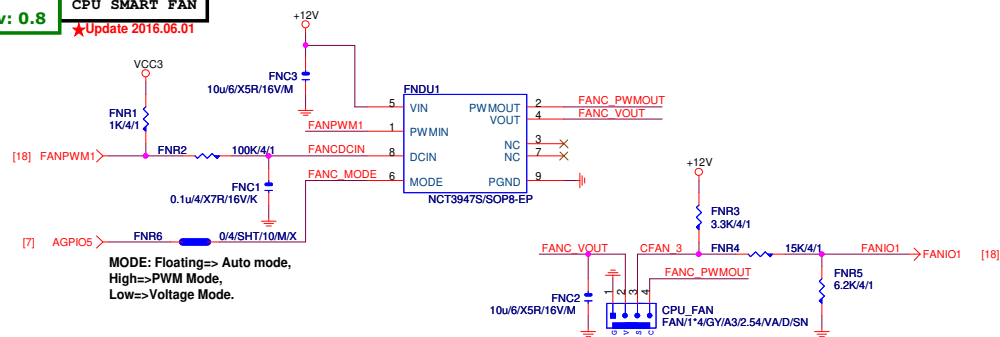
ANS 7955361

Title **PCI EXPRESS X 16**

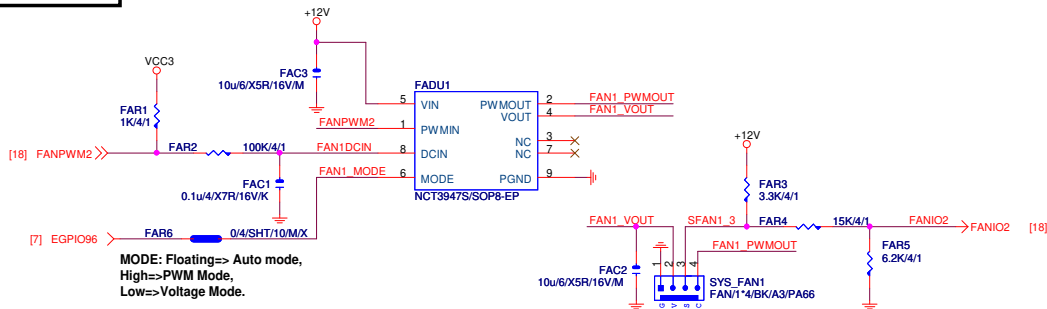
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|--------------------------------|-----------------------------------|----------------|
| Size Custom | Document Number B550M DS3H | Rev 1.0 |
| Date: Wednesday, June 10, 2020 | Sheet 16 | of 56 |



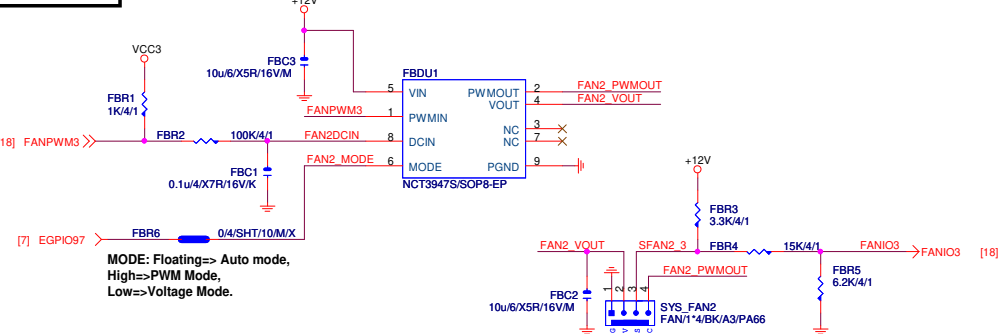




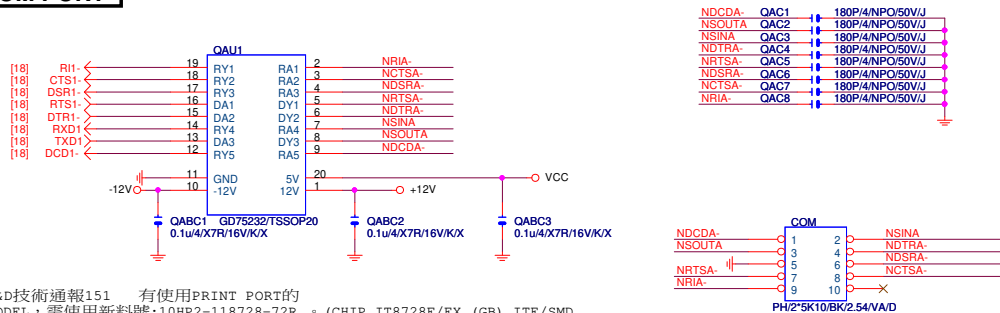
SYSTEM FAN1



SYSTEM FAN2

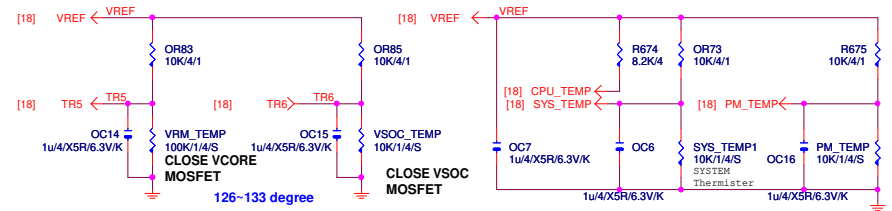


COM PORT

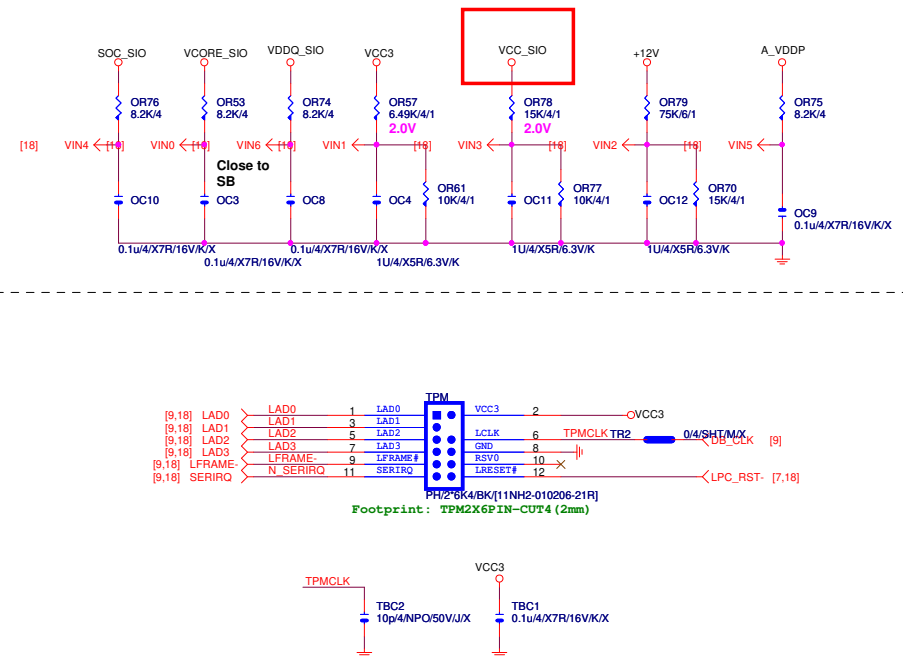


R&D技術通報151 有使用PRINT PORT的
MODEL，需使用新料號：10HP2-118728-72R。(CHIP IT8728F/EX (GB) ITE/SMD
QFP128 PRINTPORT SORTING)料件。串電阻33 ohm改為68 ohm。

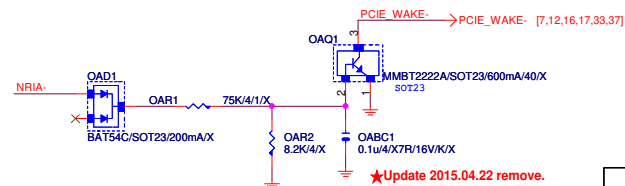
Hardware Monitor circuits - Temperature



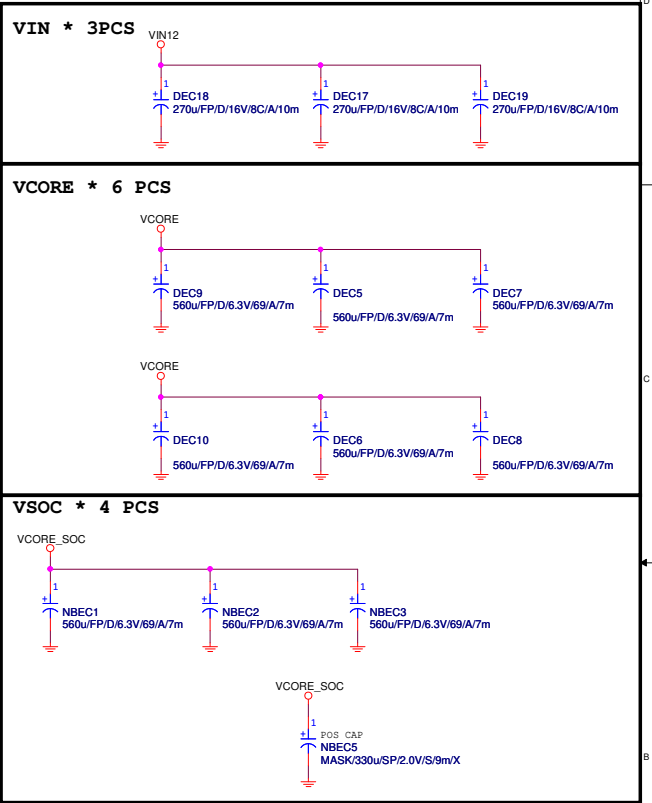
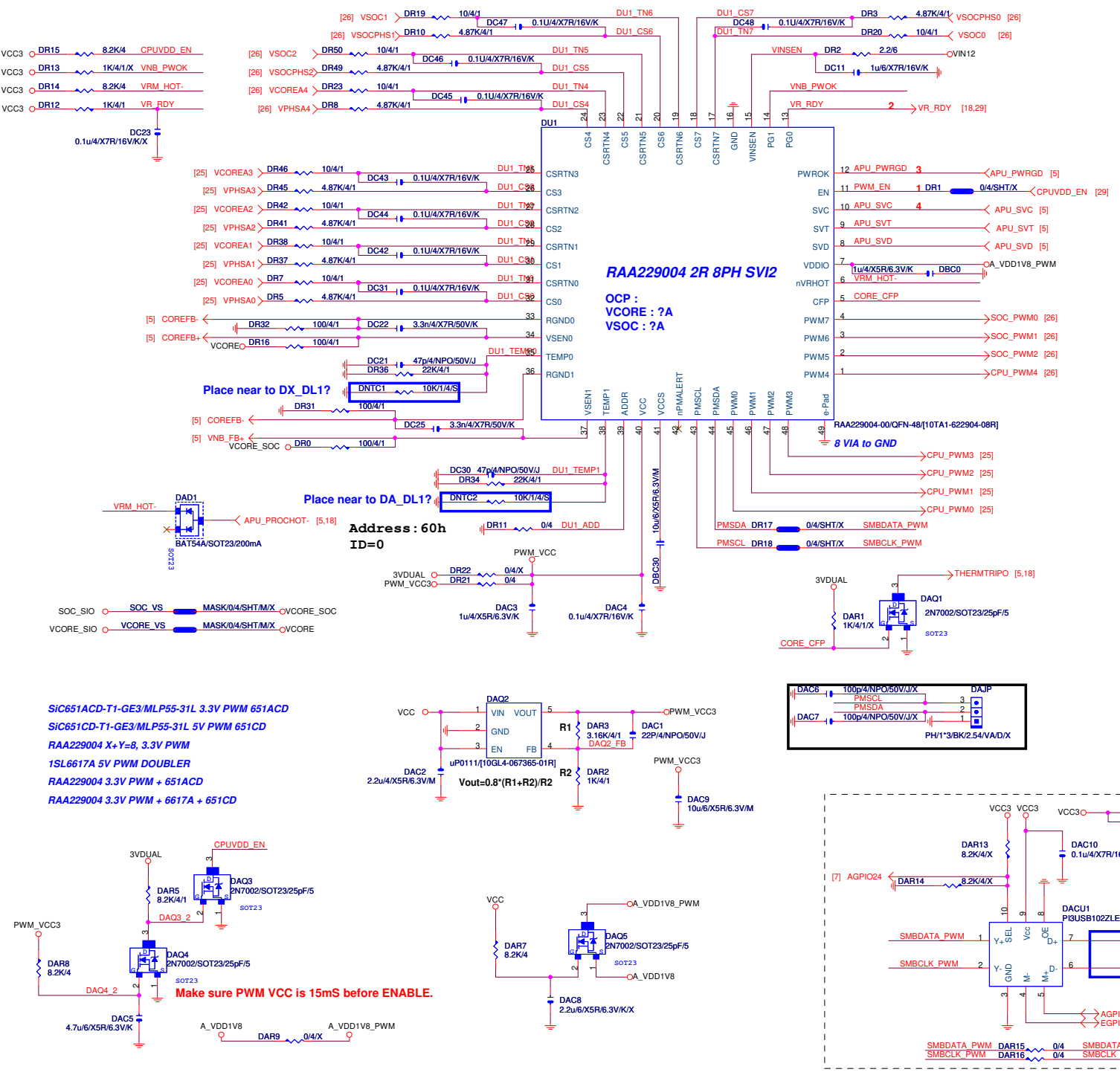
Hardware Monitor circuits - VOLTAGE



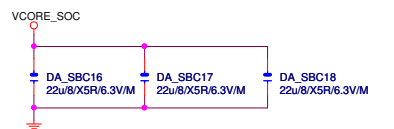
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★Update 2015.04.22 remove.



放置背板電感與電感之間

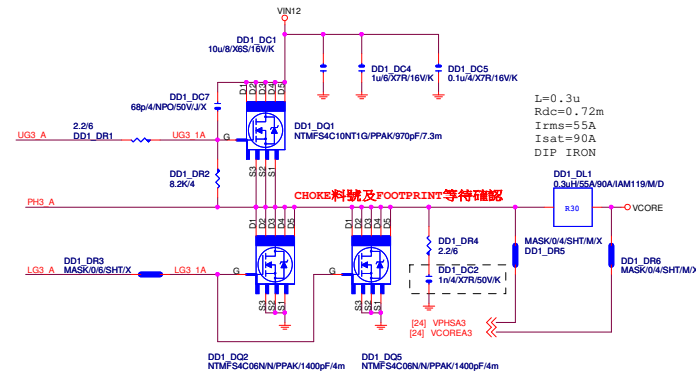
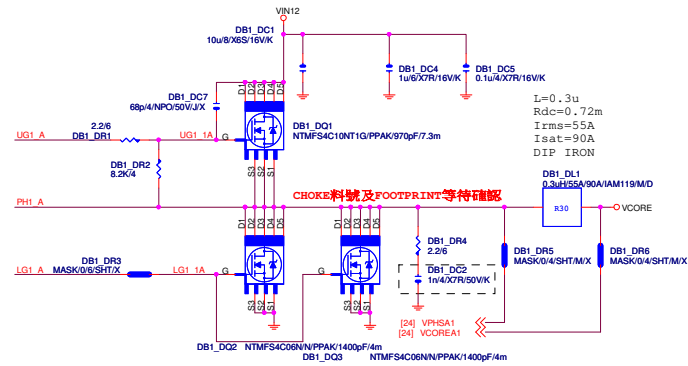
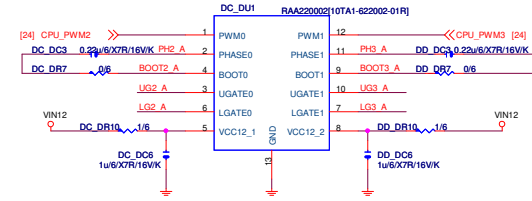
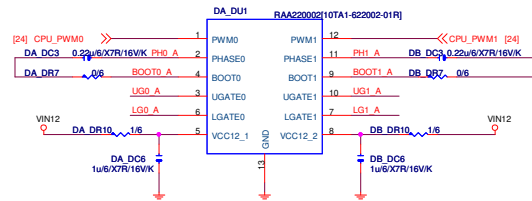
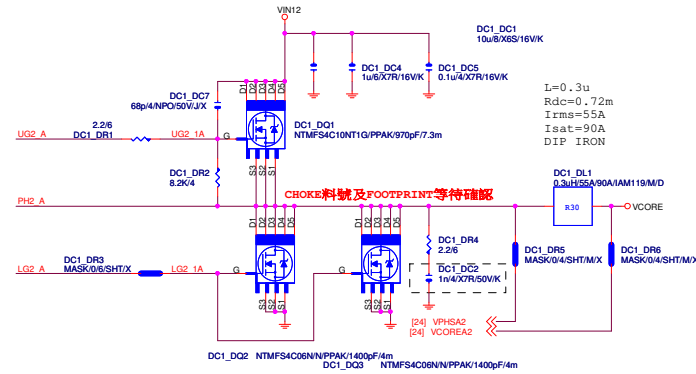
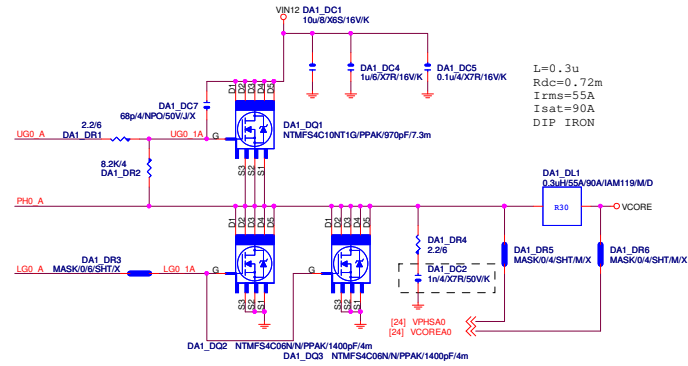


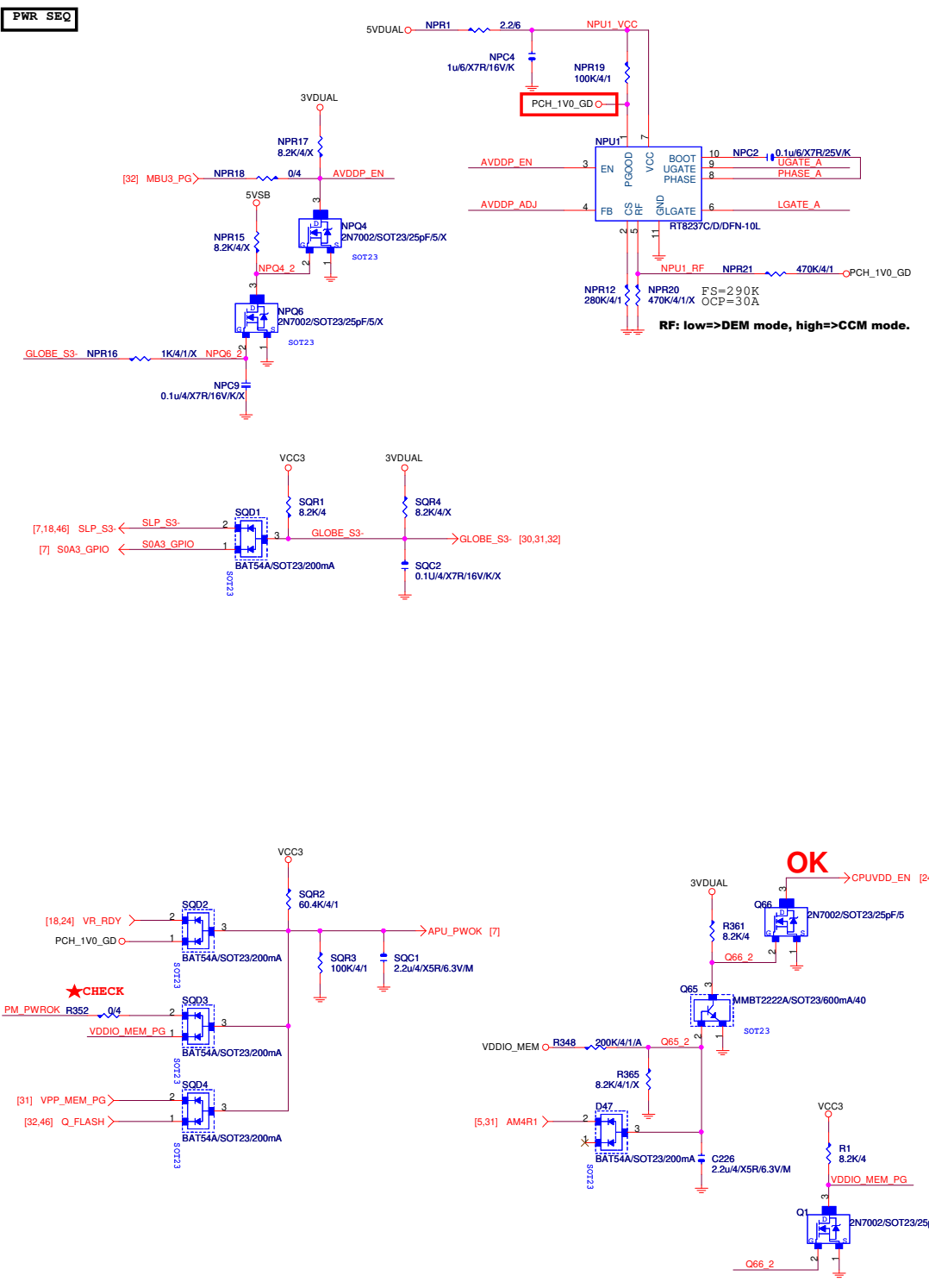
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Title**PWM RAA229004**

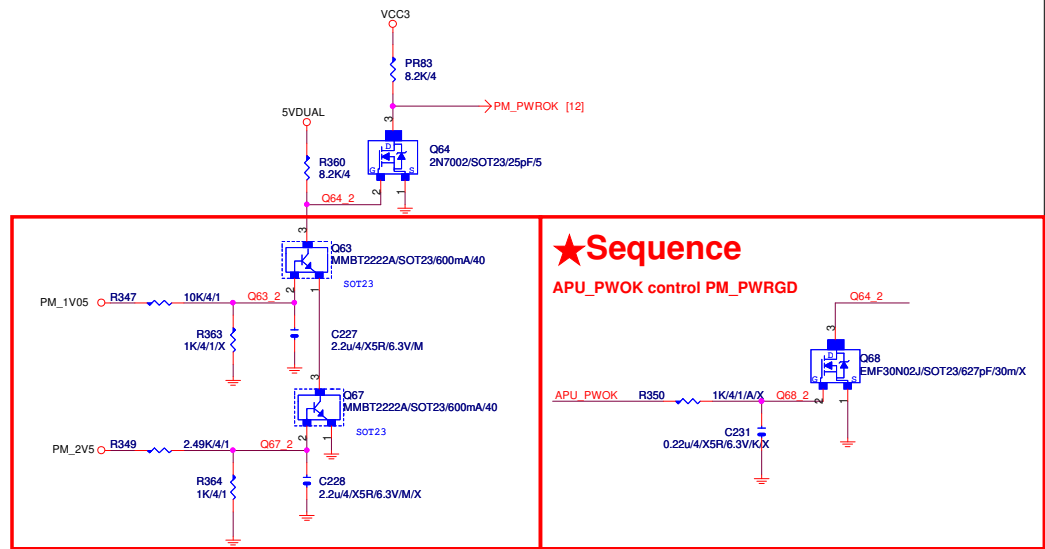
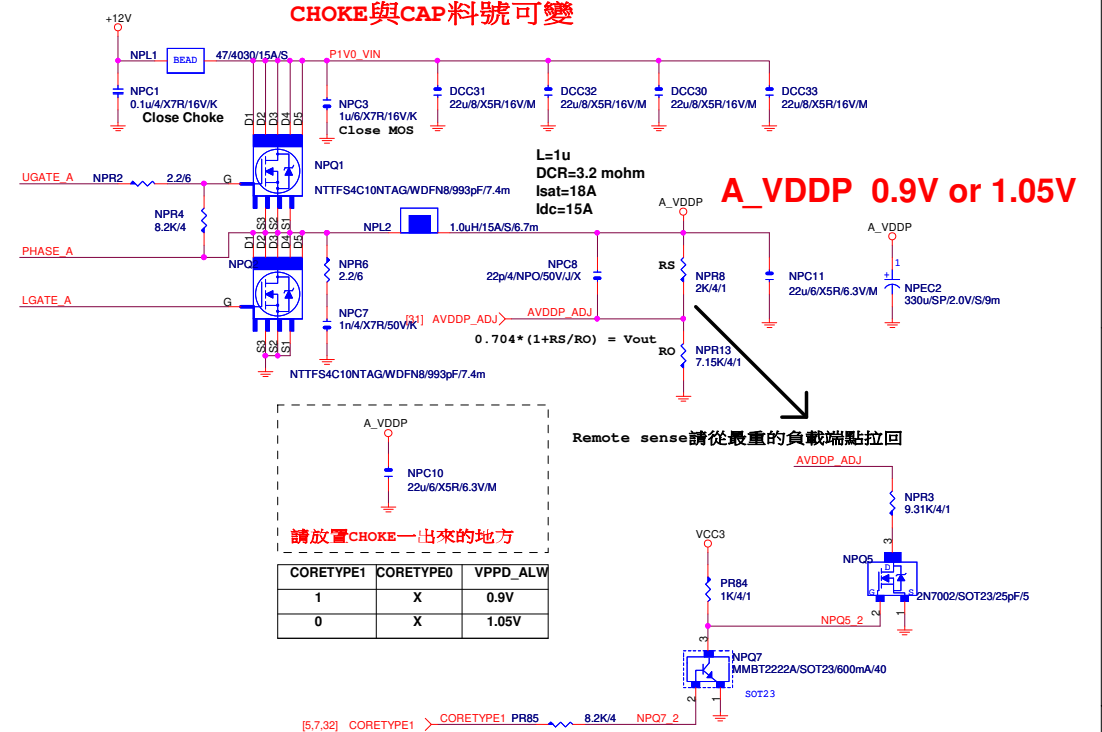
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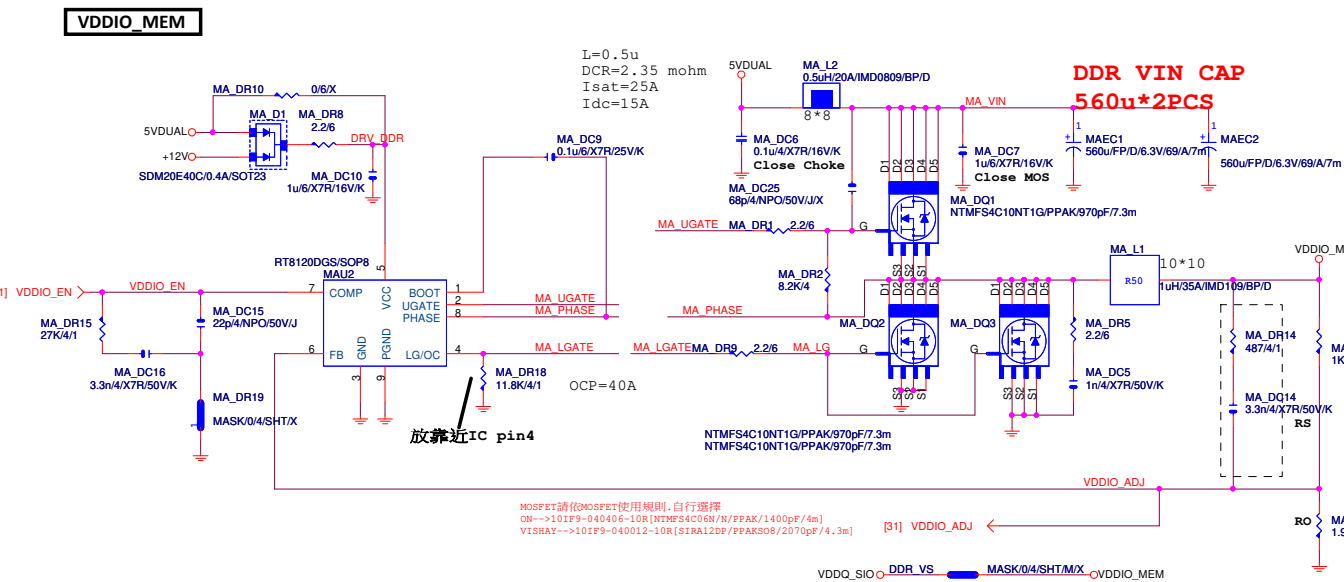
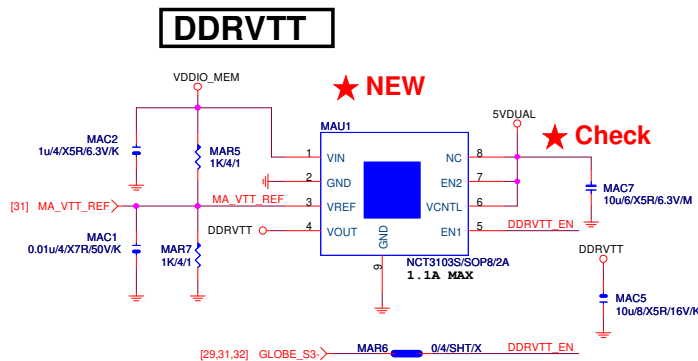
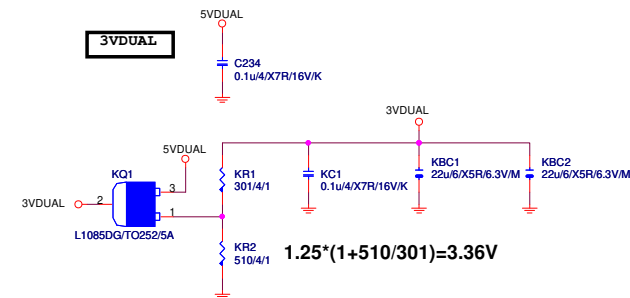
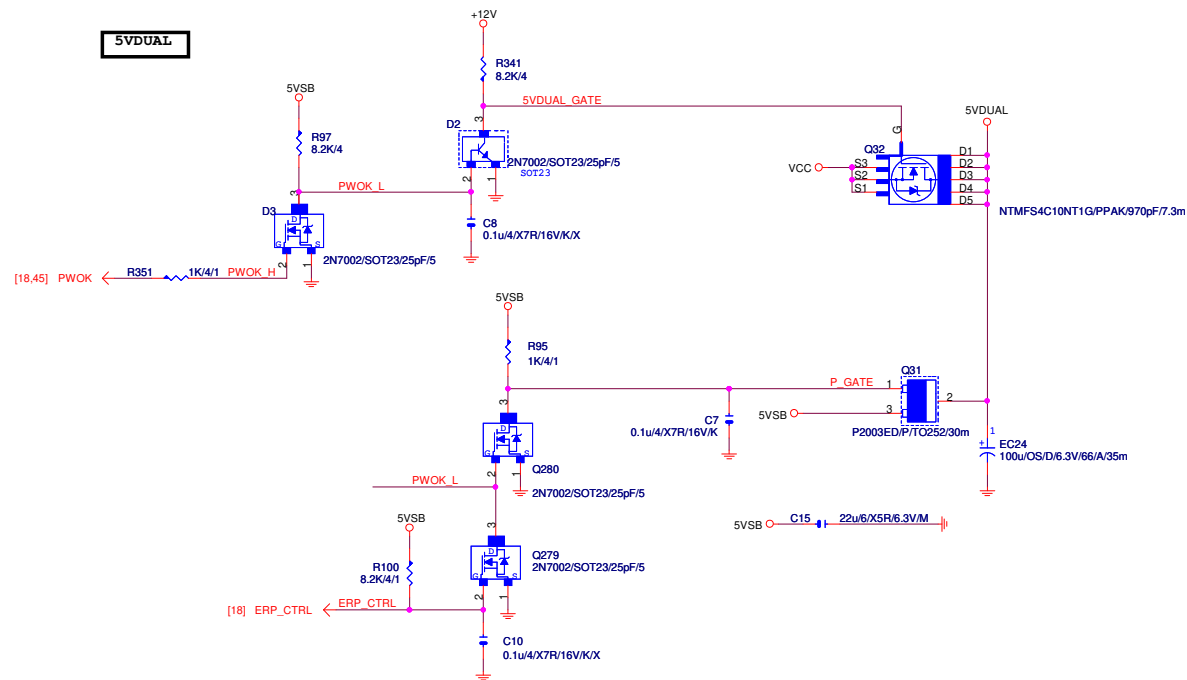
Date: Friday, May 22, 2020Sheet 24 of 56





CHOKE與CAP料號可變





SUPPORT DDR4

1.2V

25A MAX

$L=0.8\mu$
DCR=1.4 mohm
Isat=?A
Idc=28A

請放置CHOKE一出來位置,先預留.
請自行確認ripple後再決定是否上件

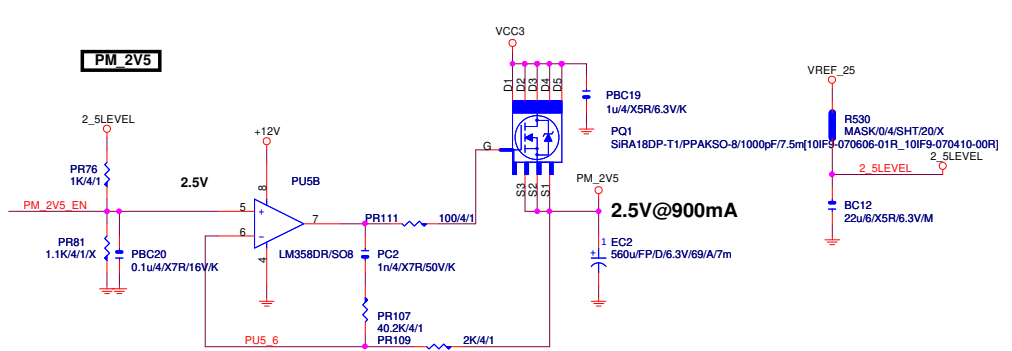
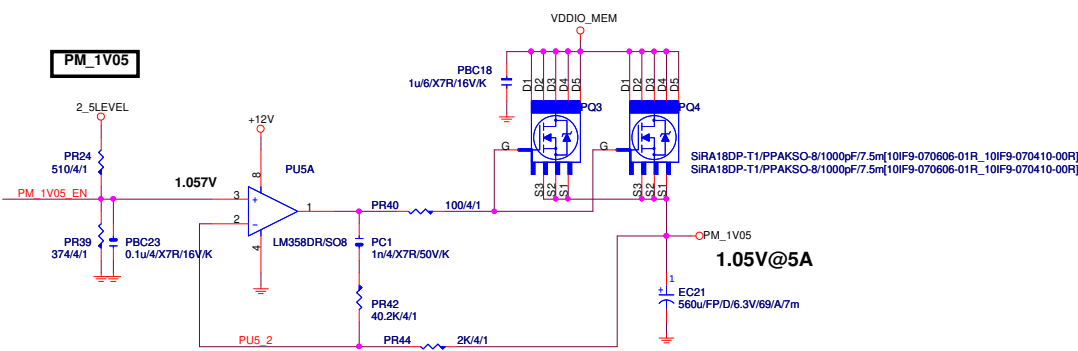
Remote sense請從最重的負載端點拉回

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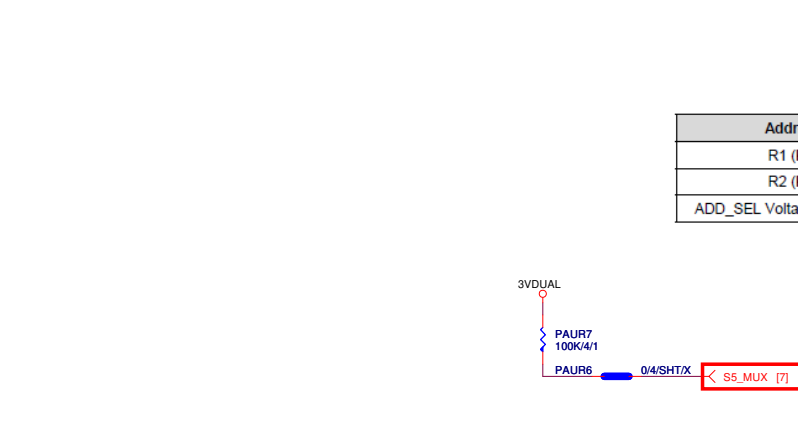
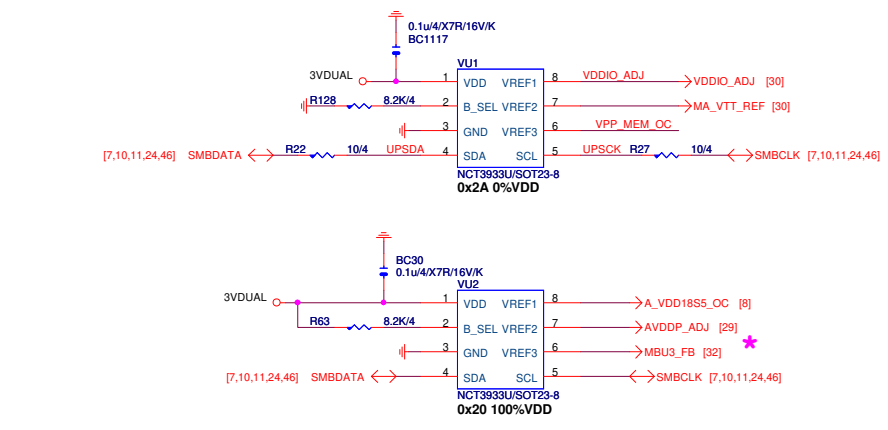
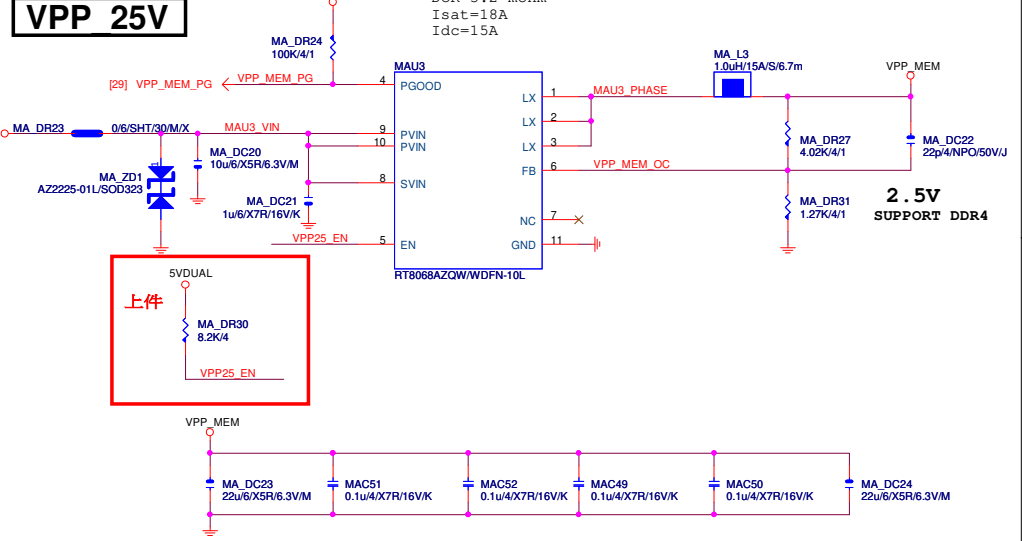
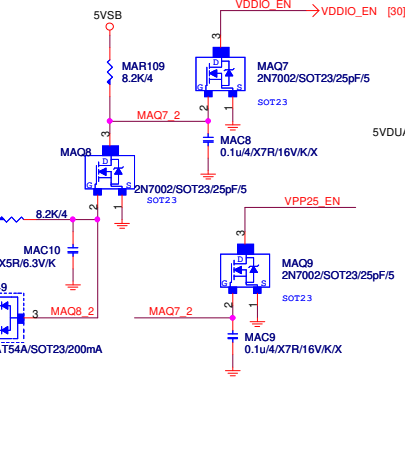
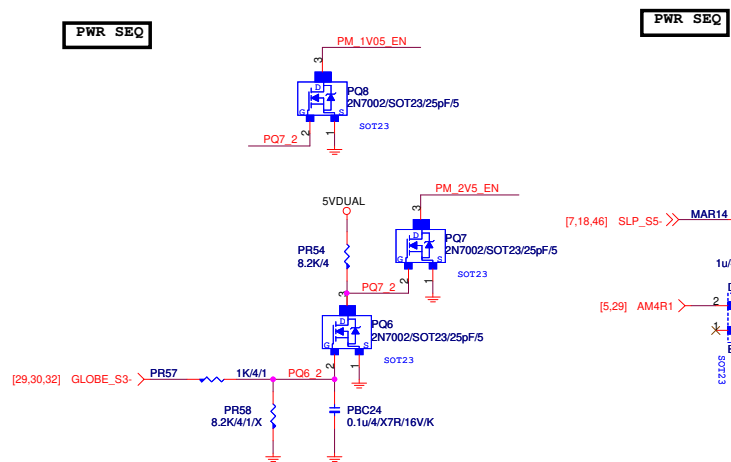
Title
DDR PWR, 5VDUAL, 3VDUAL

Size Custom Document Number B550M DS3H Rev 1.0

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| Address | 0x2A | 0x28 | 0x26 | 0x24 | 0x22 | 0x20 |
|----------------------------|------|------|------|------|------|------|
| R1 (kΩ) | open | 3.9 | 3 | 2.2 | 1.3 | 10 |
| R2 (kΩ) | 10 | 1.3 | 2.2 | 3 | 3.9 | open |
| ADD_SEL Voltage (% of VCC) | 0 | 25 | 42 | 58 | 75 | 100 |

Table1. Recommended Slave Address Setting

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Title: **VPP MEM**

Size: **B550M DS3H**

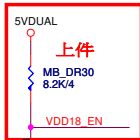
Document Number: **B550M DS3H**

Date: **Wednesday, April 22, 2020**

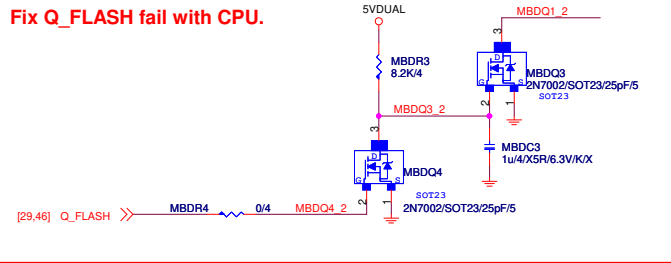
Sheet: **31** of **56**

Rev: **1.0**

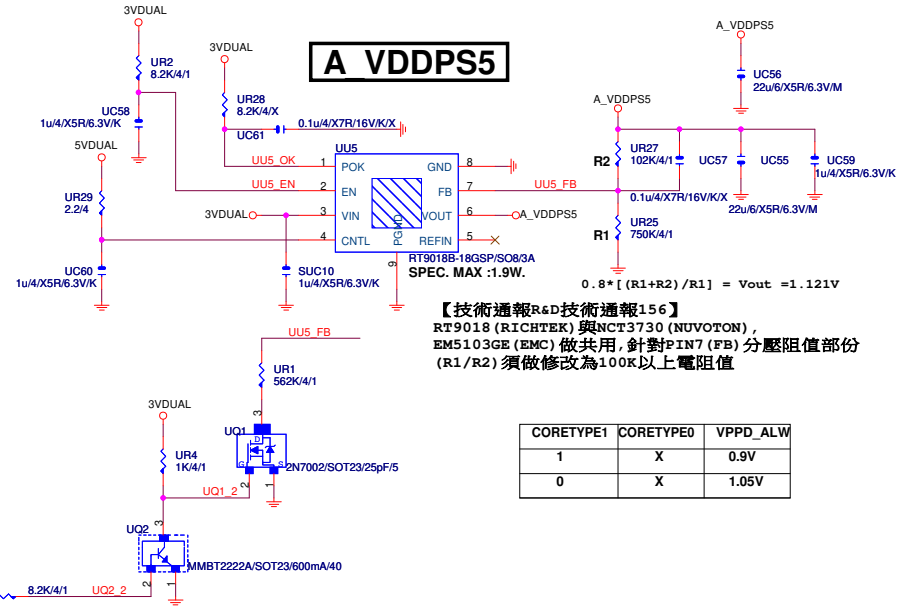
PWR_SEQ



Fix Q_FLASH fail with CPU.

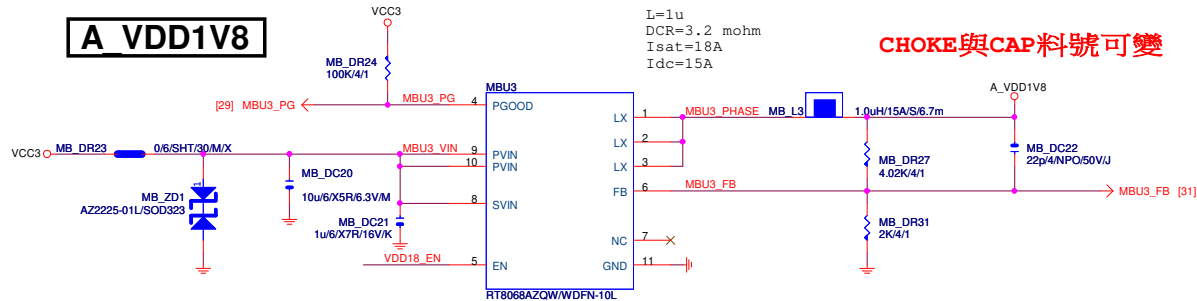


A VDDPS5

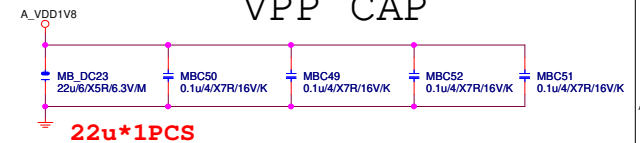


REV:0.4

A VDD1V8



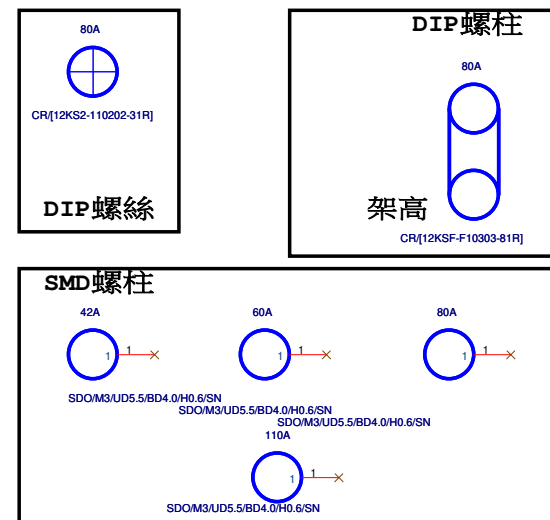
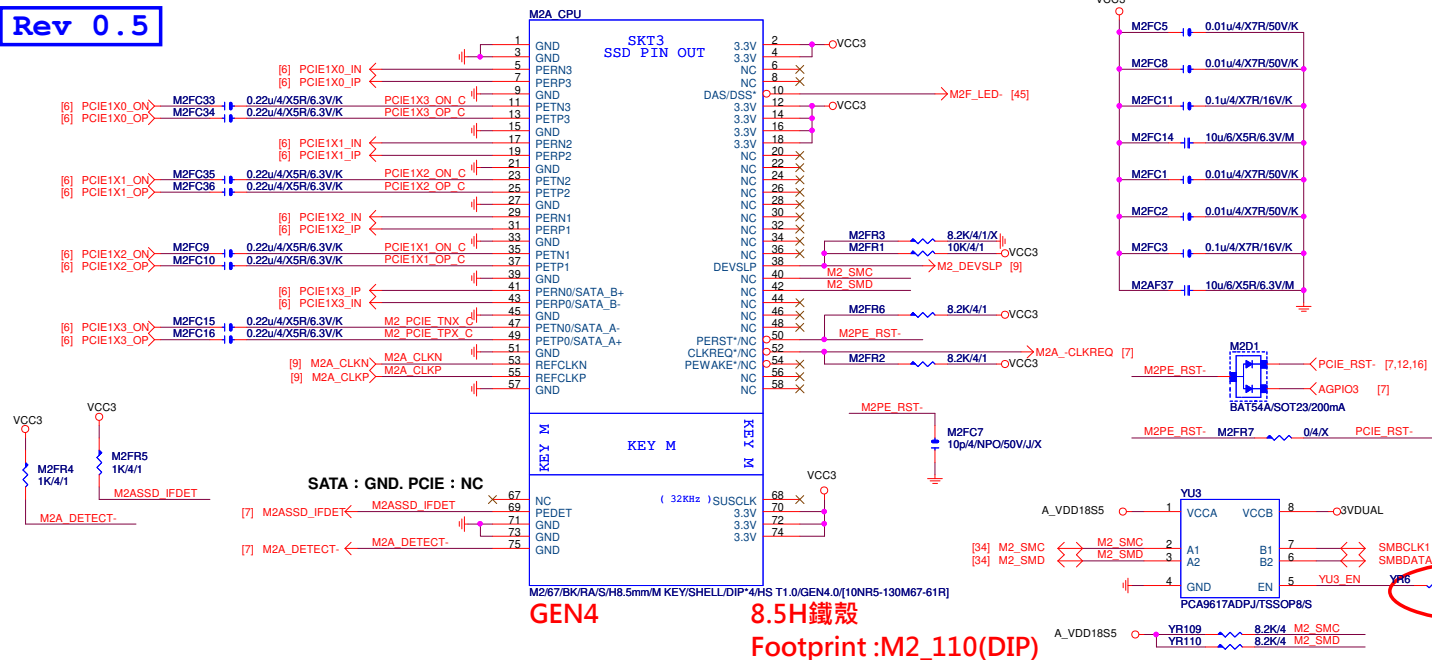
VPP CAP



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| Title | | |
|---------------|------------------------|----------------|
| FAN, A_VDD1V8 | | |
| Size | Document Number | Rev |
| Custom | B550M DS3H | 1.0 |
| Date: | Monday, April 27, 2020 | Sheet 32 of 56 |

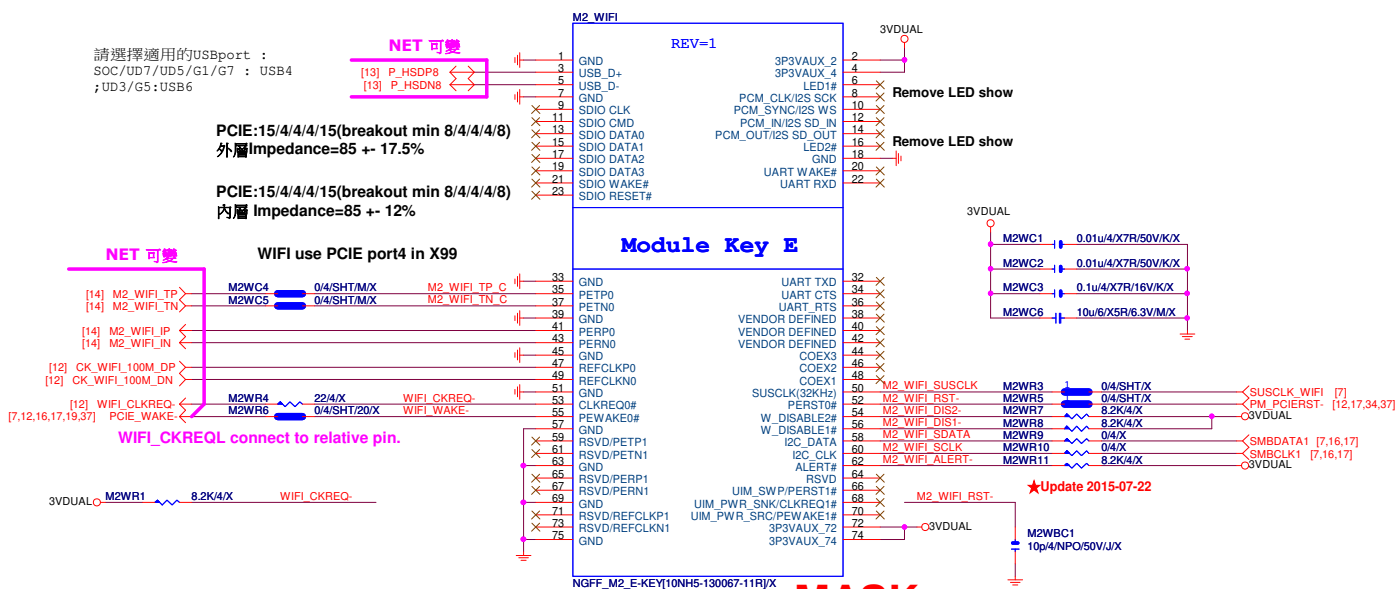
Rev 0.5



8.5H鐵殼
Footprint :M2_110(DIP)

Rev: 0.2

FOR M.2 WIFI MODULE @ REAR PANEL

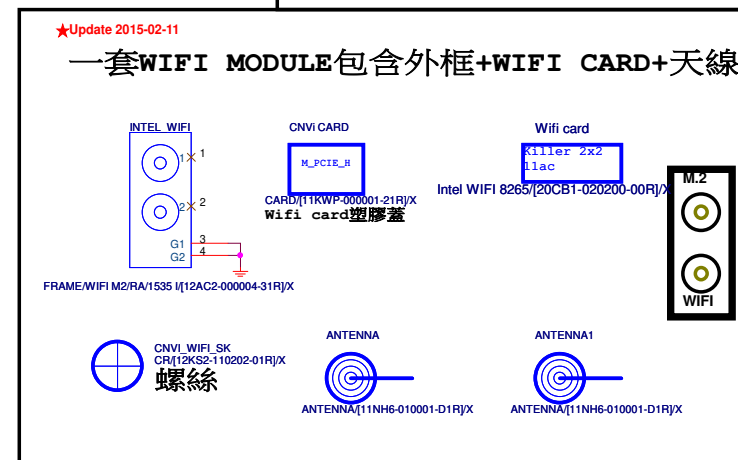


Footprint Notice.

★Update 2015-07-22
★Footprint for
直立式 SMD:
WIFI-EKEY

MASK
Footprint Notice.

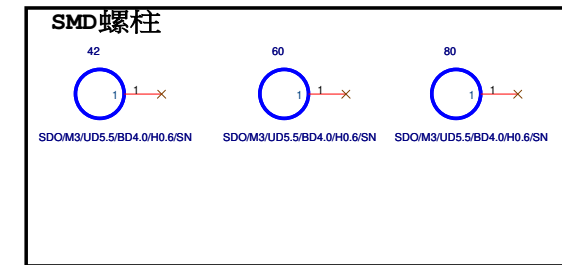
★Update 2015-07-22
★Footprint for
橫腦式SMD: NGFF-E-75P-2



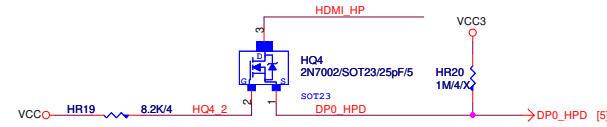
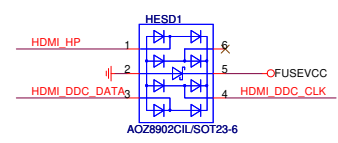
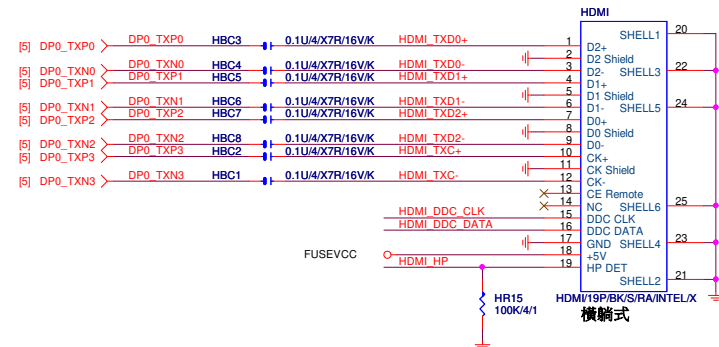
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M.2 SOCKET

| | | |
|--------------------------------|--------------------------------------|-------------------|
| Size Custom | Document Number B550M DS3H | Rev 1.0 |
| Date: Wednesday, June 03, 2020 | Sheet 33 of 56 | |

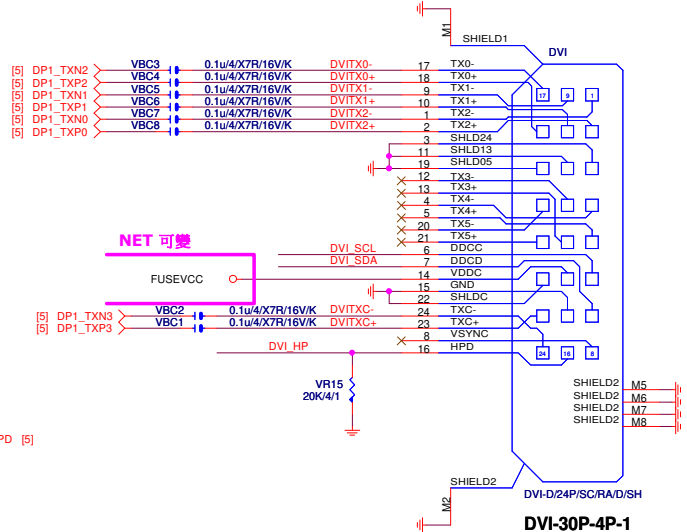
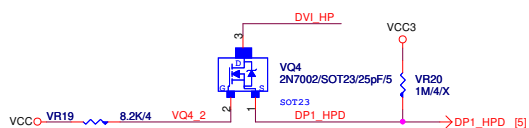
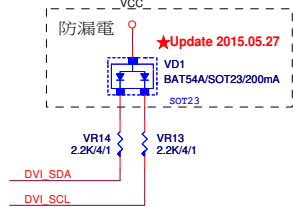


删除M2C_SOCKET & PU1

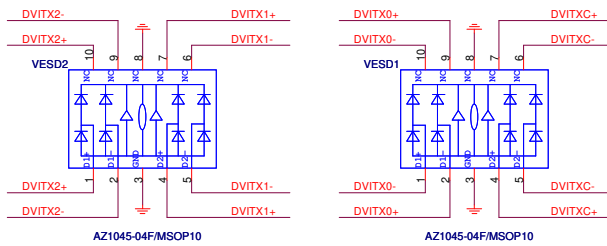


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DVI: 20/4/6/4/20
Impedance=85 +- 17.5%



Close to connector

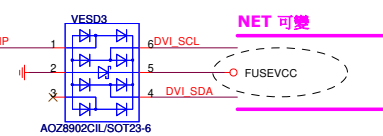


NET 可變

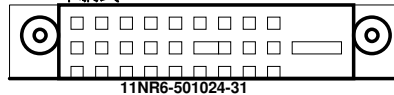
FUSEVCC

VBC10
4/X7R/16V/K

Close to connector



平躺式 DVI-D

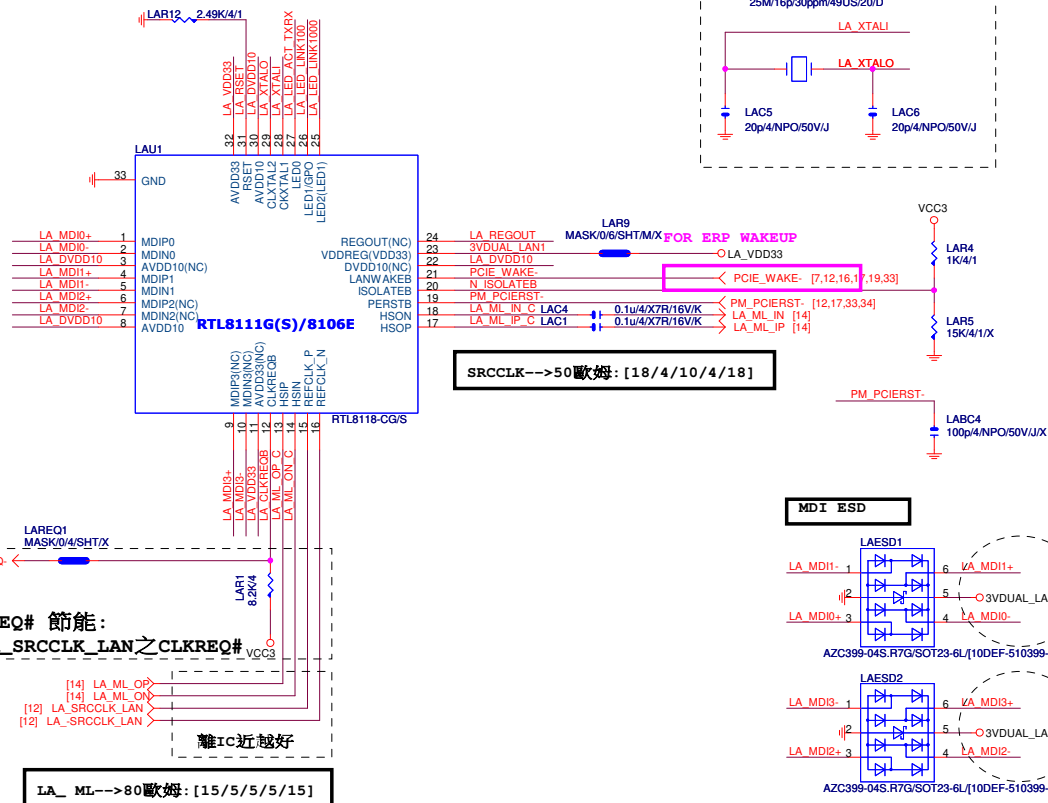


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KB_USB_DEC PWR

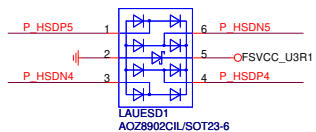
| | | |
|----------------|--------------------------------------|-------------------|
| Size Custom | Document Number B550M DS3H | Rev 1.0 |
| Date: | Wednesday, April 22, 2020 | Sheet 35 of 56 |

| | |
|--------------|-------|
| LAN:RTL8111G | R2.03 |
|--------------|-------|

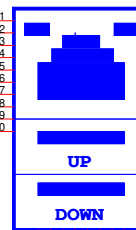
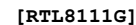
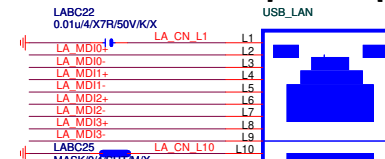


| | |
|-------------------|-------|
| USB_LAN CONNECTOR | R2.03 |
|-------------------|-------|

RMA ESD PROTECT



USB_LAN CONNECTOR

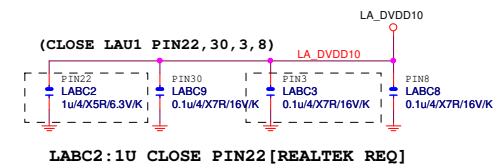


R2.0

USB+LAN/1G/GO,Y/OS/RA/D/1/15KV

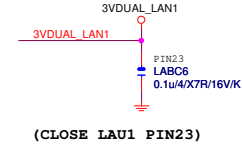
LA_MDI-->100歐姆:[20/4/8/4/20]

LAN POWER

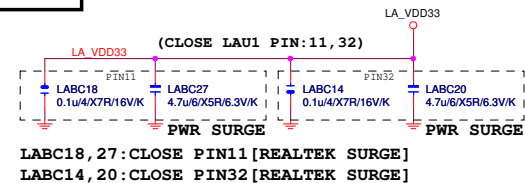


LAN POWER

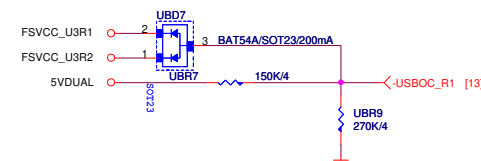
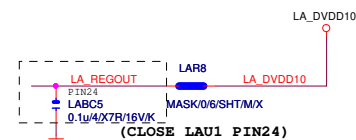
note: lan power連接及電流



LAN POWER



LAN POWER



USB POWER



Close to connector
USB_LAN 2-Port 2.0A
FUSE-0805

LAN POWER

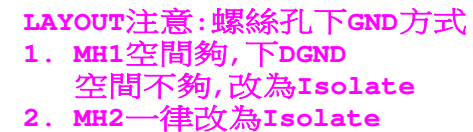


EMI

LAN AGND change GND
Remove Short Pad

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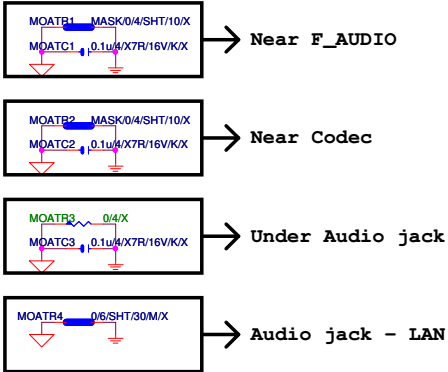
| | | | |
|----------|---------------------------|-------|----------|
| Title | | | |
| RTL8111G | | | |
| Size | Document Number | Rev | |
| Custom | B550M DS3H | 1.0 | |
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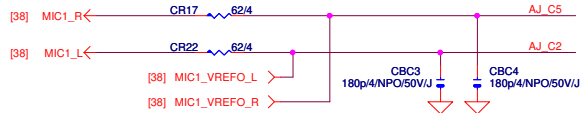
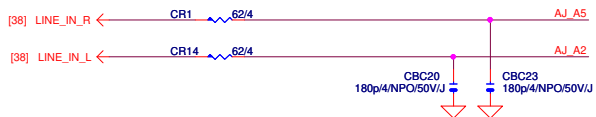
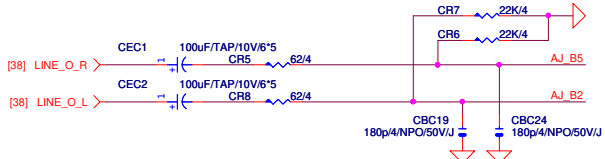
MH2 ☐ ☐

Isolate

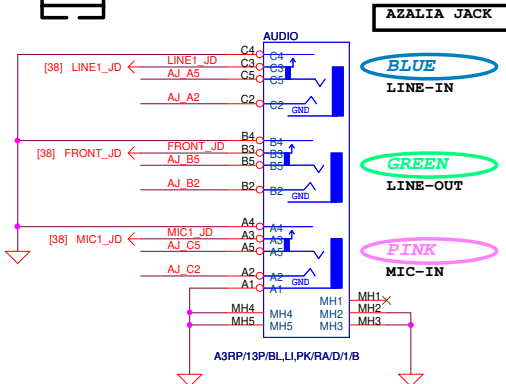
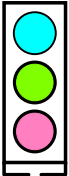
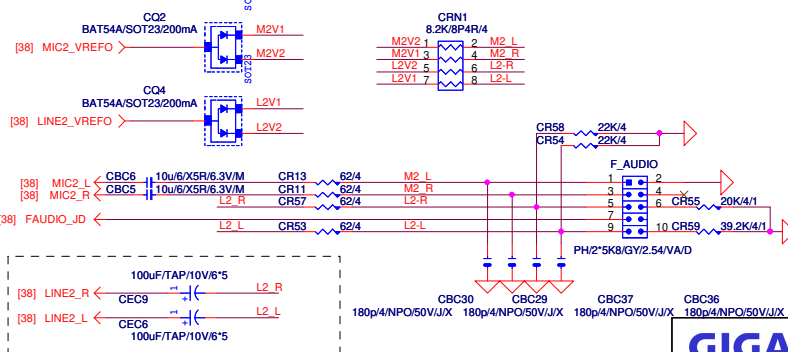
Rev 3.0

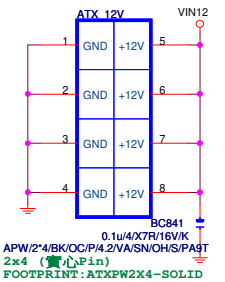
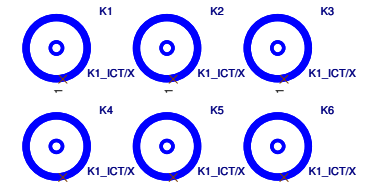
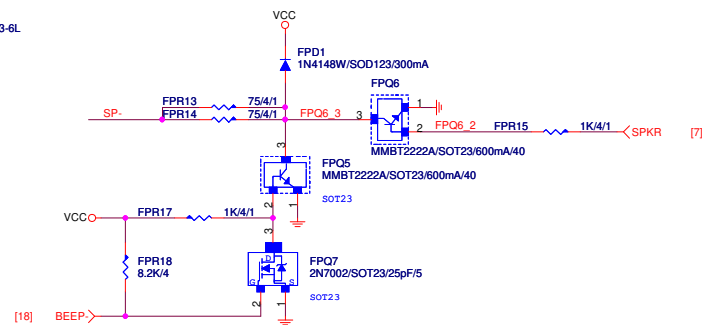
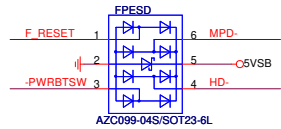
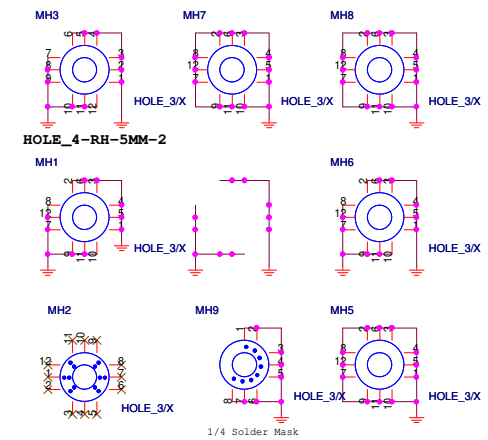
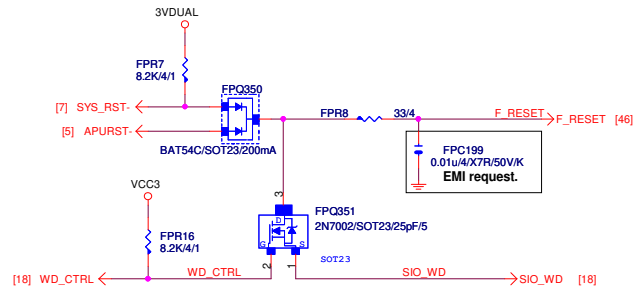


*量產前, 0ohm改short pad

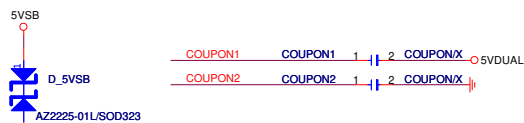
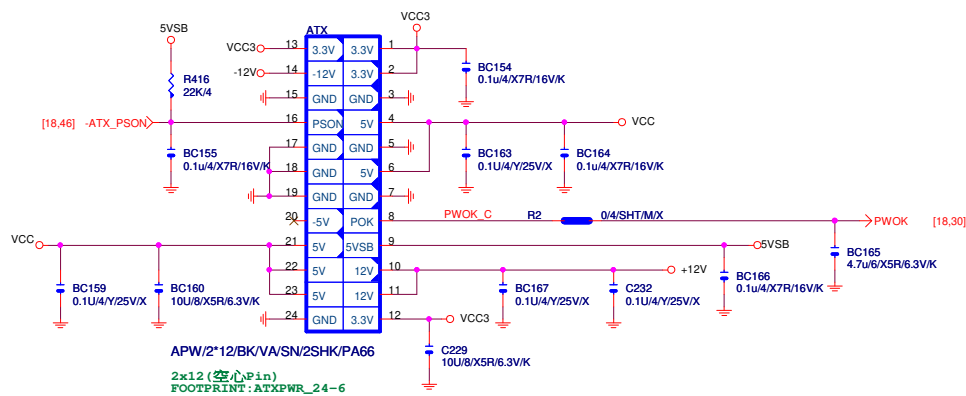


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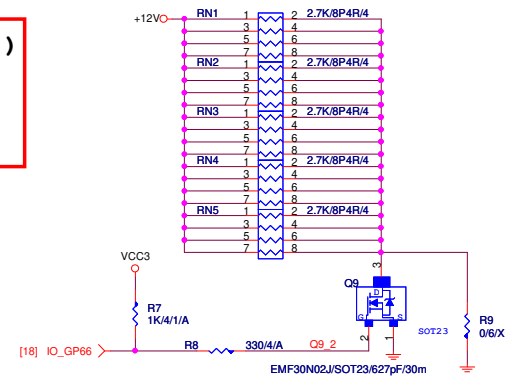




ATX POWER CONNECTOR

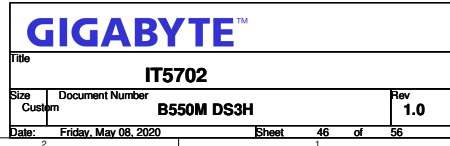


(靠近ATX CONNECTOR)



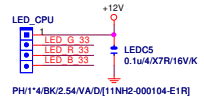
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| | | | |
|-------------------------|---------------------------|------------|----------|
| Title | | | |
| ATX, FRONT PANEL | | | |
| Size | Document Number | Rev | |
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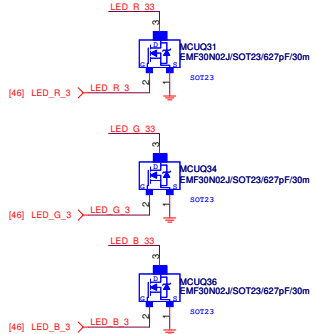
第三區 LED

燈條 LED (LED_CPU放在CPU附近位置)



Footprint "PH1X4-FAN-AMD-L"

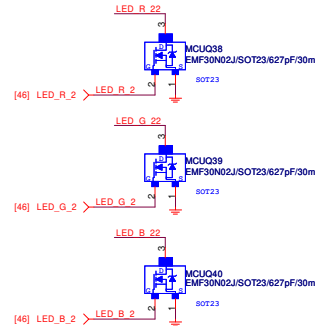
第三區 LED CONTROL



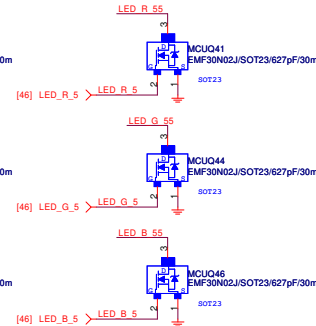
第四區 LED

第五區 LED

第二區 LED CONTROL

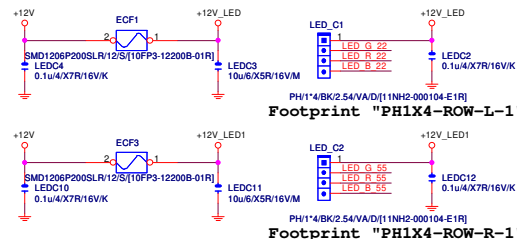


第五區 LED CONTROL



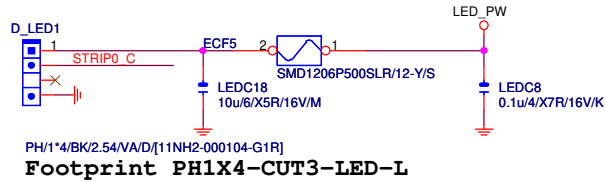
燈條 LED (LED_C1放在PCB左邊板邊位置)

燈條 LED (LED_C2放在PCB右邊板邊位置)



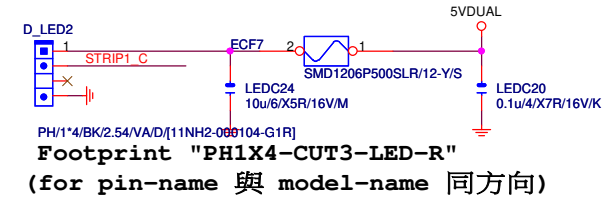
第六區 LED (靠近左上板邊位置)

Digital LED Strip1

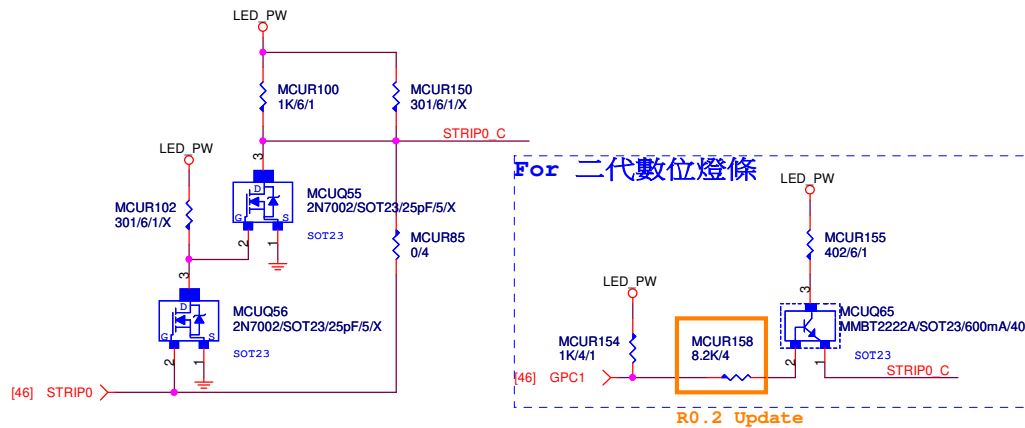


第七區 (靠近右下CPU板邊位置)

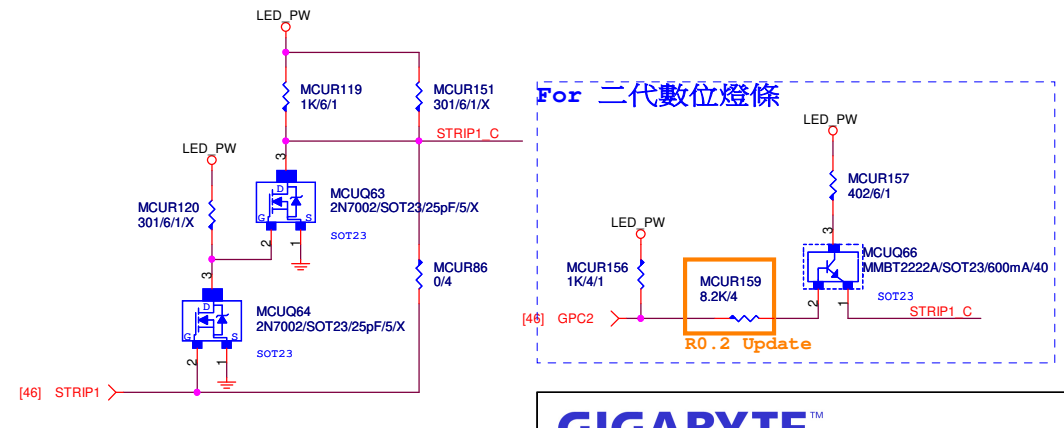
Digital LED Strip2



燈條 Level shift

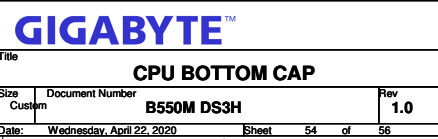


燈條 Level shift

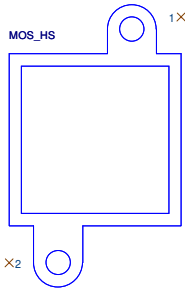
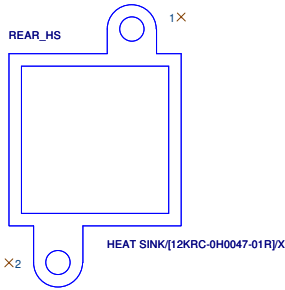
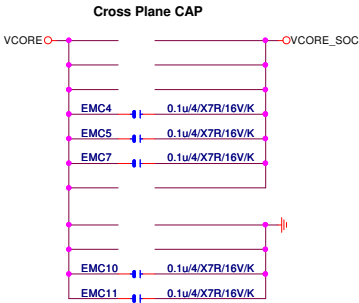
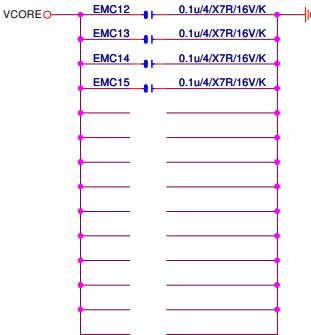
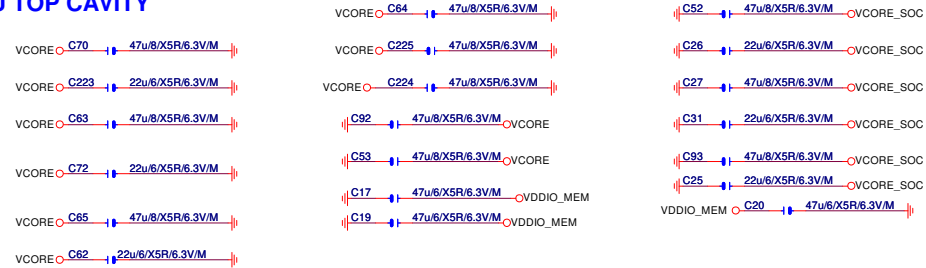


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| Title | | | |
|--------|---------------------------|-------|----------|
| D_LED | | | |
| Size | Document Number | Rev | |
| Custom | B550M DS3H | 1.0 | |
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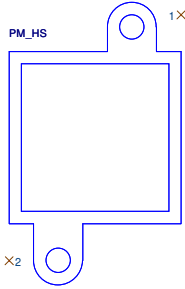
CPU TOP CAVITY



MOS_HS

T+R
Footprint :
sink_z490_ud-t

HEAT SINK[I12SP2-S09325-71R_12SP2-S09325-72R_12SP2-S09325-73R]



PM_HS

Footprint :BGAHSINK_SB-N

PM_HS[I12SP2-S03507-61R_12SP2-S03507-62R_12SP2-S03507-63R]

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| | | | | | |
|-------|--------|---------------------------|--|-------------|----------|
| Title | | | | CPU TOP CAP | |
| Size | Custom | Document Number | | | Rev |
| | | B550M DS3H | | | 1.0 |
| Date: | | Wednesday, April 22, 2020 | | Sheet | 56 of 56 |